

**HIGH-VOLTAGE MIXED-SIGNAL IC**

# UC8151

All-in-one driver IC w/ Timing Controller for  
White/Black/Red Dot-Matrix Micro-Cup ESL

**ES Specifications**  
**Datasheet Revision: 0.6**

**IC Version: d\_B**  
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Specifications and information herein are subject to change without notice.

## Table of Content

INTRODUCTION .....	3
MAIN APPLICATIONS.....	3
FEATURE HIGHLIGHTS .....	3
BLOCK DIAGRAM.....	4
ORDERING INFORMATION .....	5
PIN DESCRIPTION .....	6
COMMAND TABLE.....	8
COMMAND DESCRIPTION.....	11
HOST INTERFACES .....	30
POWER MANAGEMENT.....	32
TEMPERATURE RANGE .....	36
COMMAND DEFAULT SETTING .....	38
DEEP SLEEP MODE .....	39
PANEL BREAK CHECK .....	40
CASCADE APPLICATION CIRCUIT.....	41
BOOSTER APPLICATION CIRCUIT.....	42
ABSOLUTE MAXIMUM RATINGS .....	43
DC CHARACTERISTICS .....	44
AC CHARACTERISTICS .....	45
PHYSICAL DIMENSIONS .....	47
ALIGNMENT MARK INFORMATION .....	49
PAD COORDINATES .....	50
TRAY INFORMATION.....	57
REVISION HISTORY .....	59

# UC8151

All-in-one driver IC with Timing Controller for  
White/Black/Red Dot-Matrix Micro-Cup ESL

## INTRODUCTION

The UC8151 is an all-in-one driver with timing controller for ESL. Its output is of 1-bit white/black and 1-bit red resolution per pixel. The timing controller provides control signals for source driver and gate driver.

The DC-DC controller allows it to generate the source output voltage VDH/VDL ( $\pm 6.4V \sim \pm 15.0V$ ) and VDHR (2.4V~11.0V). The chip also includes an output buffer for the supply of the COM electrode (AC-VCOM or DC-VCOM). The system is configurable through a 3-wire/4-wire (SPI) serial interface.

## MAIN APPLICATIONS

- E-tag application

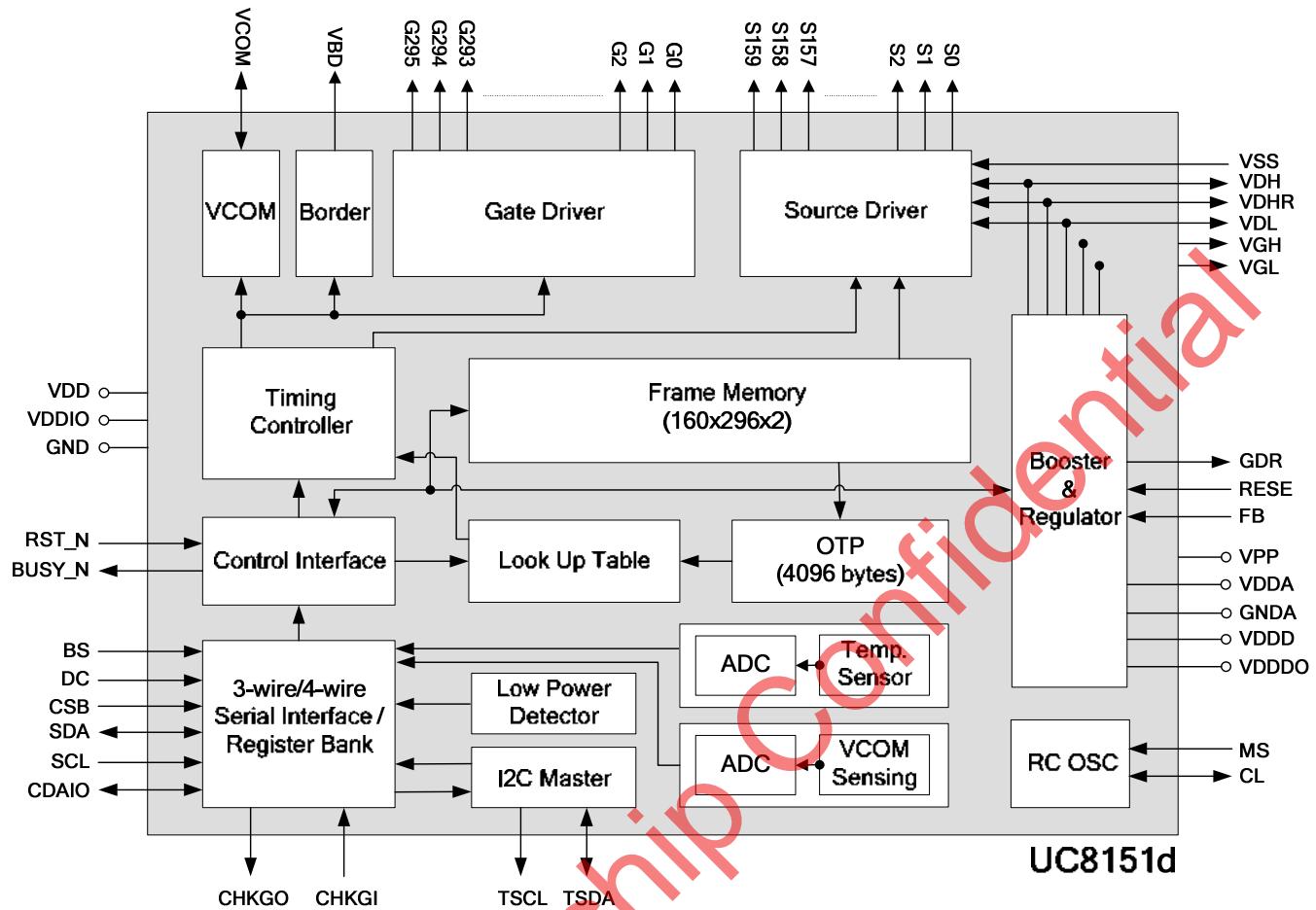
## FEATURE HIGHLIGHTS

- System-on-chip (SOC) for ESL
- Timing controller supports several resolutions
  - Up to 160 source x 296 gate resolution + 1 border + 1 VCOM
  - 1 bit for white/black and 1 bit for red per pixel
- Cascade: 2 or more chips cascade mode
- Memory (Max.): 160 x 296 x 2 bits SRAM
- 3-wire/4-wire (SPI) serial interface
  - Clock rate up to 20MHz

- Temperature sensor:
  - On-Chip:  $-25 \sim 50^{\circ}C \pm 2.0^{\circ}C$  / 8-bit status
  - Off-Chip:  $-55 \sim 125^{\circ}C \pm 2.0^{\circ}C$  / 11-bit status ( $I^2C/LM75$ )
- Support LPD, Low Power Detection ( $VDD < 2.5V$ )
- OSC / PLL: On-chip RC oscillator
- VCOM:
  - AC-VCOM / DC-VCOM (by LUT)
  - Support VCOM sensing (6-bit digital status)
- Charge Pump: On-chip booster and regulator:
  - VGH: +20V
  - VGL: -20V
  - VDH:  $+6.4 \sim +15.0V$  (programmable, black/white)
  - VDL:  $-6.4 \sim -15.0V$  (programmable, black/white)
  - VDHR:  $+2.4 \sim +11.0V$  (programmable, red)
- Digital supply voltage: 2.3~ 3.6V
- OTP: 4K-byte OTP for LUTs and Settings
- Package: COG
- Source/Gate bump information
  - Bump pitch:  $13 \mu M \pm 2 \mu M$
  - Bump space:  $1 \mu M \pm 3 \mu M$
  - Bump surface:  $1200 \mu M^2$

**Remark:** Contact UltraChip for a visual inspection document (03-DOC-093).

## BLOCK DIAGRAM



## ORDERING INFORMATION

Part Number	Description
UC8151dHAB-U0P1-4	4-inch tray, wafer thickness 180uM
UC8151dHAB-U0P1-3	3-inch tray, wafer thickness 180uM
UC8151dHAB-U0X3-4	4-inch tray, wafer thickness 300uM
UC8151dHAB-U0X3-3	3-inch tray, wafer thickness 300uM

### General Notes

#### APPLICATION INFORMATION

For improved readability, the specification contains many application data points. When application information is given, it is advisory and does not form part of the specification for the device.

#### BARE DIE DISCLAIMER

All die are tested and are guaranteed to comply with all data sheet limits up to the point of wafer sawing. There is no post waffle saw/pack testing performed on individual die. Although the latest modern processes are utilized for wafer sawing and die pick-&-place into waffle pack carriers, UltraChip has no control of third party procedures in the handling, packing or assembly of the die. Accordingly, it is the responsibility of the customer to test and qualify their application in which the die is to be used. UltraChip assumes no liability for device functionality or performance of the die or systems after handling, packing or assembly of the die.

#### LIFE SUPPORT APPLICATIONS

These devices are not designed for use in life support appliances, or systems where malfunction of these products can reasonably be expected to result in personal injuries. Customer using or selling these products for use in such applications do so at their own risk.

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**PIN DESCRIPTION**

Type: I: Input, O: Output, I/O: Input/Output, PWR: Power, C: Capacitor pin

Pin (Pad) Name	Pin Count	Type	Description
<b>POWER SUPPLY PINS</b>			
VDD	7	PWR	Digital power
VDDA	10	PWR	Analog power
VDDIO	10	PWR	IO power
VDDDO	4	PWR	Digital power output (1.8V)
VDDD (VDDI)	4	PWR	Digital power input (1.8V)
VPP	6	PWR	OTP program power (7.75V)
VDM	4	PWR	Analog Ground.
GND	18	PWR	Digital Ground.
GNDA	17	PWR	Analog Ground
<b>LDO PINS</b>			
VDH (VSH)	10	I/O	Positive source driver Voltage (+6.4V ~ +15V)
VDHR	8	I/O	Positive source driver voltage for Red (+2.4V ~ +11V)
VDL (VSL)	10	I/O	Negative source driver voltage (-6.4V ~ -15V)
<b>CONTROL INTERFACE PINS</b>			
BS	1	I	Bus Selection. Select 3-wire / 4-wire SPI interface L: 4-wire interface. H: 3-wire interface.
RST_N	1	I (Pull-up)	Global reset pin. Low: active. When RST_N becomes low, driver will reset. All register will reset to default value. Driver all function will disable. Source/Gate/Border/VCOM will be released to floating. The minimal width of RST_N=low is 50us.
MS	1	I	Cascade setting pin. L: Slave chip. H: Master chip.
CL	1	I/O	Clock input/output pin. Master: Clock output. Slave: Clock input.
CDAIO	1	I/O	Cascade data pin. Leave it open if not used.
BUSY_N	1	O	Driver busy flag. L: Driver is Busy. H: Host side can send command/data to driver.
<b>MCU INTERFACE (SPI) PINS</b>			
CSB	1	I	Serial communication chip select.
SDA	1	I/O	Serial communication data input/output
SCL	1	I	Serial communication clock input.
DC	1	I	Command/Data input. L: command H: data Connect to GND if BS=High.

Pin (Pad) Name	Pin Count	Type	Description
<b>I<sup>2</sup>C INTERFACE</b>			
TSCL	2	O (open-drain)	I <sup>2</sup> C clock (External pull-up resistor is necessary.) Leave them open if not used.
TSDA	2	I/O (open-drain)	I <sup>2</sup> C data (External pull-up resistor is necessary.) Leave them open if not used.
<b>OUTPUT PINS</b>			
S0~S159 ( S<0>~S<159> )	160	O	Source driver output signals.
G0~G295 ( G<0>~G<295> )	296	O	Gate driver output signals.
VCOM	16	O	VCOM output.
VBD (VBD<1>, VBD<2>)	1, 1	O	Border output pins.
<b>BOOSTER PINS</b>			
GDR	8	O	N-MOS gate control
RESE	2	P	Current sense input for control loop.
FB	2	P	(Keep Open.)
VGH	12	I/O	Positive Gate voltage.
VGL	16	I/O	Negative Gate voltage.
<b>CHECK PANEL PINS</b>			
CHKGI	1	I (Pull-down)	Check panel break input. Leave open if it is not used.
CHKGO	1	O	Check panel break output. Leave open if it is not used.
<b>RESERVED PINS</b>			
VSYNC	1	O	Reserved pins. Leave it floating.
TEST1~TEST3	3	I	Reserved pins. Leave it floating or connected to VSS.
TEST6, TEST7	2	O	Reserved pins. Leave it floating.
DUMMY	15	-	Reserved pins. Leave it floating.
NC	32	-	Not Connected.

**COMMAND TABLE**

W/R: 0: Write Cycle 1: Read Cycle

C/D: 0: Command / 1: Data

D7~D0: -: Don't Care #: Valid Data

#	Command	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	Registers	Default
1	Panel Setting (PSR)	0	0	0	0	0	0	0	0	0	0		00H
		0	1	#	#	#	#	#	#	#	#	RES[1:0],REG,KW/R,UD,SHL, SHD_N,RST_N	0FH
2	Power Setting (PWR)	0	0	0	0	0	0	0	0	0	1		01H
		0	1	--	--	--	--	--	--	#	#	VDS_EN, VDG_EN	03H
		0	1	--	--	--	--	--	#	#	#	VCOM_HV,VGHL_LV[1:0]	00H
		0	1	--	--	#	#	#	#	#	#	VDH[5:0]	26H
		0	1	--	--	#	#	#	#	#	#	VDL[5:0]	26H
		0	1	--	--	#	#	#	#	#	#	VDHR[5:0]	03H
3	Power OFF (POF)	0	0	0	0	0	0	0	0	1	0		02H
4	Power OFF Sequence Setting (PFS)	0	0	0	0	0	0	0	0	1	1		03H
		0	1	--	--	#	#	--	--	--	--	T_VDS_OF[1:0]	00H
5	Power ON (PON)	0	0	0	0	0	0	0	1	0	0		04H
6	Power ON Measure (PMES)	0	0	0	0	0	0	0	1	0	1		05H
7	Booster Soft Start (BTST)	0	0	0	0	0	0	0	1	1	0		06H
		0	1	#	#	#	#	#	#	#	#	BT_PHA[7:0]	17H
		0	1	#	#	#	#	#	#	#	#	BT_PHB[7:0]	17H
		0	1	--	--	#	#	#	#	#	#	BT_PHC[5:0]	17H
8	Deep sleep (DSLP)	0	0	0	0	0	0	0	1	1	1		07H
		0	1	1	0	1	0	0	1	0	1	Check code	A5H
9	Display Start Transmission 1 (DTM1, White/Black Data) (x-byte command)	0	0	0	0	0	1	0	0	0	0	B/W or OLD Pixel Data (160x296):	10H
		0	1	#	#	#	#	#	#	#	#	KPXL[1:8]	00H
		0	1	:	:	:	:	:	:	:	:	:	:
		0	1	#	#	#	#	#	#	#	#	KPXL[n-1:n]	00H
10	Data Stop (DSP)	0	0	0	0	0	1	0	0	0	1		11H
		1	1	#	--	--	--	--	--	--	--		00H
11	Display Refresh (DRF)	0	0	0	0	0	1	0	0	1	0		12H
12	Display Start transmission 2 (DTM2, Red Data) (x-byte command)	0	0	0	0	0	1	0	0	1	1	Red or NEW Pixel Data (160X296):	13H
		0	1	#	#	#	#	#	#	#	#	RPXL[1:8]	00H
		0	1	:	:	:	:	:	:	:	:	:	:
		0	1	#	#	#	#	#	#	#	#	RPXL[n-1:n]	00H
13	Auto Sequence (AUTO)	0	0	0	0	0	1	0	1	1	1		17H
		1	1	1	0	1	0	0	1	0	1	Check code	A5H
14	LUT option (LUTOPT)	0	0	0	0	1	0	1	0	1	0		2AH
		0	1	--	--	#	#	#	#	#	#	STATE_XON[5:0]	00H
		0	1	--	--	#	#	--	#	#	#	EXS[1:0], DMS[2:0]	00H
15	PLL control (PLL)	0	0	0	0	1	1	0	0	0	0		30H
		0	1	--	--	#	#	#	#	#	#	M[2:0], N[2:0]	3CH
16	Temperature Sensor Calibration (TSC)	0	0	0	1	0	0	0	0	0	0		40H
		1	1	#	#	#	#	#	#	#	#	D[10:3] / TS[7:0]	00H
		1	1	#	#	#	--	--	--	--	--	D[2:0] / -	00H
17	Temperature Sensor Selection (TSE)	0	0	0	1	0	0	0	0	0	1		41H
		0	1	#	--	--	--	#	#	#	#	TSE,TO[3:0]	00H

#	Command	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	Registers	Default
18	Temperature Sensor Write (TSW)	0	0	0	1	0	0	0	0	1	0		42H
		0	1	#	#	#	#	#	#	#	#	WATTR[7:0]	00H
		0	1	#	#	#	#	#	#	#	#	WMSB[7:0]	00H
		0	1	#	#	#	#	#	#	#	#	WLSB[7:0]	00H
19	Temperature Sensor Read (TSR)	0	0	0	1	0	0	0	0	1	1		43H
		1	1	#	#	#	#	#	#	#	#	RMSB[7:0]	00H
		1	1	#	#	#	#	#	#	#	#	RLSB[7:0]	00H
20	Panel Break Check (PBC)	0	0	0	1	0	0	0	1	0	0		44H
21	VCOM and data interval setting (CDI)	1	1	--	--	--	--	--	--	--	#	PSTA	00H
		0	0	0	1	0	1	0	0	0	0	VBD[1:0], DDX[1:0], CDI[3:0]	50H
22	Lower Power Detection (LPD)	0	0	0	1	0	1	0	0	0	1		51H
		1	1	--	--	--	--	--	--	--	#	LPD	01H
23	TCON setting (TCON)	0	0	0	1	1	0	0	0	0	0		60H
		0	1	#	#	#	#	#	#	#	#	S2G[3:0], G2S[3:0]	22H
24	Resolution setting (TRES)	0	0	0	1	1	0	0	0	0	1		61H
		0	1	#	#	#	#	#	0	0	0	HRES[7:3]	00H
		0	1	--	--	--	--	--	--	--	#	VRES[8:0]	00H
		0	1	#	#	#	#	#	#	#	#		00H
25	Gate/Source Start setting (GSST)	0	0	0	1	1	0	0	1	0	1		65H
		0	1	#	#	#	#	#	0	0	0	HST[7:3]	00H
		0	1	--	--	--	--	--	--	--	#	VST[8:0]	00H
		0	1	#	#	#	#	#	#	#	#		00H
26	Revision (REV)	0	0	0	1	1	1	0	0	0	0		70H
		1	1	#	#	#	#	#	#	#	#	LUT_REV[7:0]	FFH
		1	1	--	--	--	#	#	#	#	#	CHIP_REV[3:0]	0DH
27	Get Status (FLG)	0	0	0	1	1	1	0	0	0	1		71H
		1	1	--	#	#	#	#	#	#	#	PTL_FLAG, I <sup>2</sup> C_ERR, I <sup>2</sup> C_BUSYN, DATA_FLAG, PON, POF, BUSY_N	13H
28	Auto Measurement VCOM (AMV)	0	0	1	0	0	0	0	0	0	0		80H
		0	1	--	--	#	#	#	#	#	#	AMVT[1:0], XON, AMVS, AMV, AMVE	10H
29	Read VCOM Value (VV)	0	0	1	0	0	0	0	0	0	1		81H
		1	1	--	--	#	#	#	#	#	#	VV[5:0]	00H
30	VCOM_DC Setting (VDCS)	0	0	0	1	0	0	0	0	0	1		82H
		0	1	--	--	#	#	#	#	#	#	VDCS[5:0]	00H
31	Partial Window (PTL)	0	0	1	0	0	1	0	0	0	0		90H
		0	1	#	#	#	#	#	0	0	0	HRST[7:3]	00H
		0	1	#	#	#	#	#	1	1	1	HRED[7:3]	07H
		0	1	--	--	--	--	--	--	--	#	VRST[8:0]	00H
		0	1	#	#	#	#	#	#	#	#		00H
		0	1	--	--	--	--	--	--	--	#	VRED[8:0]	00H
		0	1	#	#	#	#	#	#	#	#		00H
		0	1	--	--	--	--	--	--	--	#	PT_SCAN	01H
32	Partial In (PTIN)	0	0	1	0	0	1	0	0	0	1		91H
33	Partial Out (PTOUT)	0	0	1	0	0	1	0	0	1	0		92H
34	Program Mode (PGM)	0	0	1	0	1	0	0	0	0	0		A0H
35	Active Programming (APG)	0	0	1	0	1	0	0	0	0	1		A1H

#	Command	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	Registers	Default
36	Read OTP (ROTP)	0	0	1	0	1	0	0	0	1	0		A2H
		1	1	--	--	--	--	--	--	--	--	Read Dummy	N/A
		1	1	#	#	#	#	#	#	#	#	Data of Address = 000h	N/A
		1	1	:	:	:	:	:	:	:	:	:	N/A
		1	1	#	#	#	#	#	#	#	#	Data of Address = n	N/A
37	Cascade Setting (CCSET)	0	0	1	1	1	0	0	0	0	0		E0H
		0	1	--	--	--	--	--	--	#	#	TSFIX, CCEN	00H
38	Power Saving (PWS)	0	0	1	1	1	0	0	0	1	1		E3H
		0	1	#	#	#	#	#	#	#	#	VCOM_W[3:0], SD_W[3:0]	00H
39	LVD Voltage Select (LVSEL)	0	0	1	1	1	0	0	1	0	0		E4H
		0	1	--	--	--	--	--	--	#	#	LVD_SEL[1:0]	03H
40	Force Temperature (TSSET)	0	0	1	1	1	0	0	1	0	1		E5H
		0	1	#	#	#	#	#	#	#	#	TS_SET[7:0]	00H

**Note:** (1) All other register addresses are invalid or reserved by UltraChip, and should NOT be used.

- (2) Any bits shown here as 0 must be written with a 0. All unused bits should also be set to zero. Device malfunction may occur if this is not done.
- (3) Commands are processed on the 'stop' condition of the interface.
- (4) Registers marked 'W/R' can be read, but the contents are written when the SPI command completes – so the contents can be read and altered. The user can subsequently write the register to restore the contents following an SPI read.

**COMMAND DESCRIPTION**

[W/R]: 0: Write Cycle / 1: Read Cycle    [C/D]: 0: Command / 1: Data    [D7-D0]: -: Don't Care

**(1) PANEL SETTING (PSR) (REGISTER: R00H)**

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Setting the panel	0	0	0	0	0	0	0	0	0	0	00H
	0	1	RES1	RES0	REG	KW/R	UD	SHL	SHD_N	RST_N	0FH

**RES[1:0]:** Display Resolution setting (source x gate)

**00b: 96x230 (Default)** Active source channels: S0 ~ S95. Active gate channels: G0 ~ G229.

01b: 96x252

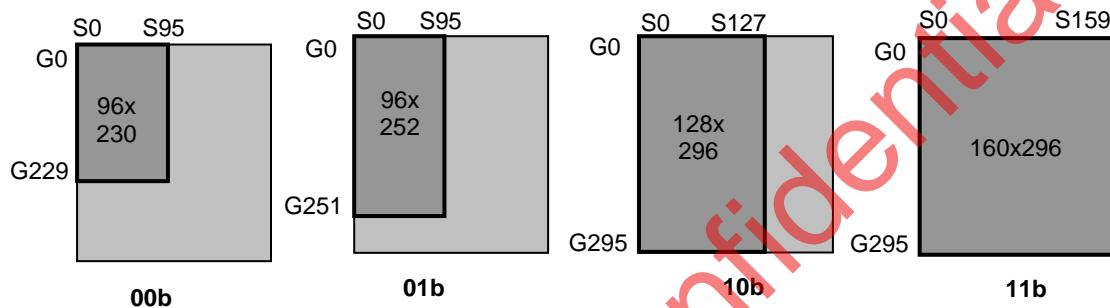
Active source channels: S0 ~ S95. Active gate channels: G0 ~ G251.

10b: 128x296

Active source channels: S0 ~ S127. Active gate channels: G0 ~ G295.

11b: 160x296

Active source channels: S0 ~ S159. Active gate channels: G0 ~ G295.



(1) Minimum active GD is always G0 regardless of <UD>(R00H).

(2) Minimum active SD is always S0 regardless of <SHL>(R00H).

**REG:** LUT selection

**0: LUT from OTP. (Default)**

1: LUT from register.

**KW/R:** Black / White / Red

**0: Pixel with Black/White/Red, KWR mode. (Default)**

1: Pixel with Black/White, KW mode.

**UD:** Gate Scan Direction

0: Scan down.

First line to Last line: Gn-1 → Gn-2 → Gn-3 → ... → G0

**1: Scan up. (Default)**

First line to Last line: G0 → G1 → G2 → ... → Gn-1

**SHL:** Source Shift Direction

0: Shift left.

First data to Last data: Sn-1 → Sn-2 → Sn-3 → ... → S0

**1: Shift right. (Default)**

First data to Last data: S0 → S1 → S2 → ... → Sn-1

**SHD\_N:** Booster Switch

0: Booster OFF

**1: Booster ON (Default)**

When SHD\_N becomes LOW, charge pump will be turned OFF, register and SRAM data will keep until VDD OFF. And Source/Gate/Border/VCOM will be released to floating.

**RST\_N:** Soft Reset

0: Reset. Booster OFF, Register data are set to their default values, all drivers will be reset, and all functions will be disabled. Source/Gate/Border/VCOM will be released to floating.

**1: No effect (Default).**

## (2) POWER SETTING (PWR) (R01H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Selecting Internal/External Power	0	0	0	0	0	0	0	0	0	1	01H
	0	1	-	-	-	-	-	-	VDS_EN	VDG_EN	03H
	0	1	-	-	-	-	-	-	VCOM_HV	VGHL_LV[1:0]	00H
	0	1	-	-	-	-	-	-	VDH[5:0]		26H
	0	1	-	-	-	-	-	-	VDL[5:0]		26H
	0	1	-	-	-	-	-	-	VDHR[5:0]		03H

**VDS\_EN:** Source power selection

0 : External source power from VDH/VDL/VDHR pins

1 : Internal DC/DC function for generating VDH/VDL/VDHR. (Default)

**VDG\_EN:** Gate power selection

0 : External gate power from VGH/VGL pins

1 : Internal DC/DC function for generating VGH/VGL. (Default)

**VCOM\_HV:** VCOM Voltage Level

0 : VCOMH=VDH+VCOM\_DC, VCOML=VDL+VCOM\_DC. (Default)

1 : VCOMH=VGH, VCOML=VGL

**VGHL\_LV[1:0]:** VGH / VGL Voltage Level selection.

VGHL_LV	VGHL Voltage Level
00 (Default)	VGH=20V, VGL= -20V
01	VGH=19V, VGL= -19V
10	VGH=18V, VGL= -18V
11	VGH=17V, VGL= -17V

**VDH[5:0]:** Internal VDH power selection for B/W pixel. (Default value: 100110b)

VDH	Voltage	VDH	Voltage	VDH	Voltage	VDH	Voltage
000000	6.4 V	001100	8.8 V	011000	11.2 V	100100	13.6 V
000001	6.6 V	001101	9.0 V	011001	11.4 V	100101	13.8 V
000010	6.8 V	001110	9.2 V	011010	11.6 V	<b>100110</b>	<b>14.0 V</b>
000011	7.0 V	001111	9.4 V	011011	11.8 V	100111	14.2 V
000100	7.2 V	010000	9.6 V	011100	12.0 V	101000	14.4 V
000101	7.4 V	010001	9.8 V	011101	12.2 V	101001	14.6 V
000110	7.6 V	010010	10.0 V	011110	12.4 V	101010	14.8 V
000111	7.8 V	010011	10.2 V	011111	12.6 V	101011	15.0 V
001000	8.0 V	010100	10.4 V	100000	12.8 V	(others)	15.0 V
001001	8.2 V	010101	10.6 V	100001	13.0 V		
001010	8.4 V	010110	10.8 V	100010	13.2 V		
001011	8.6 V	010111	11.0 V	100011	13.4 V		

**VDL[5:0]:** Internal VDL power selection for B/W pixel. (Default value: 100110b)

VDL	Voltage	VDL	Voltage	VDL	Voltage	VDL	Voltage
000000	-6.4 V	001100	-8.8 V	011000	-11.2 V	100100	-13.6 V
000001	-6.6 V	001101	-9.0 V	011001	-11.4 V	100101	-13.8 V
000010	-6.8 V	001110	-9.2 V	011010	-11.6 V	<b>100110</b>	<b>-14.0 V</b>
000011	-7.0 V	001111	-9.4 V	011011	-11.8 V	100111	-14.2 V
000100	-7.2 V	010000	-9.6 V	011100	-12.0 V	101000	-14.4 V
000101	-7.4 V	010001	-9.8 V	011101	-12.2 V	101001	-14.6 V
000110	-7.6 V	010010	-10.0 V	011110	-12.4 V	101010	-14.8 V
000111	-7.8 V	010011	-10.2 V	011111	-12.6 V	101011	-15.0 V
001000	-8.0 V	010100	-10.4 V	100000	-12.8 V	(others)	-15.0 V
001001	-8.2 V	010101	-10.6 V	100001	-13.0 V		
001010	-8.4 V	010110	-10.8 V	100010	-13.2 V		
001011	-8.6 V	010111	-11.0 V	100011	-13.4 V		

**VDHR[5:0]: Internal VDHR power selection for Red pixel. (Default value: 000011b)**

VDHR	Voltage	VDHR	Voltage	VDHR	Voltage	VDHR	Voltage
000000	2.4 V	001100	4.8 V	011000	7.2 V	100100	9.6 V
000001	2.6 V	001101	5.0 V	011001	7.4 V	100101	9.8 V
000010	2.8 V	001110	5.2 V	011010	7.6 V	100110	10.0V
<b>000011</b>	<b>3.0 V</b>	001111	5.4 V	011011	7.8 V	100111	10.2 V
000100	3.2 V	010000	5.6 V	011100	8.0 V	101000	10.4 V
000101	3.4 V	010001	5.8 V	011101	8.2V	101001	10.6 V
000110	3.6 V	010010	6.0 V	011110	8.4 V	101010	10.8 V
000111	3.8 V	010011	6.2 V	011111	8.6 V	101011	11.0 V
001000	4.0 V	010100	6.4 V	100000	8.8 V	(others)	11.0 V
001001	4.2 V	010101	6.6 V	100001	9.0 V		
001010	4.4 V	010110	6.8 V	100010	9.2 V		
001011	4.6 V	010111	7.0 V	100011	9.4 V		

### (3) POWER OFF (POF) (R02H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Turning OFF the power	0	0	<b>0</b>	<b>0</b>	<b>0</b>	<b>0</b>	<b>0</b>	<b>0</b>	<b>1</b>	<b>0</b>	02H

After the Power OFF command, the driver will be powered OFF. Refer to the POWER MANAGEMENT section for the sequence.

This command will turn off booster, controller, source driver, gate driver, VCOM, and temperature sensor, but register data will be kept until VDD turned OFF or Deep Sleep Mode. Source/Gate/Border/VCOM will be released to floating.

### (4) POWER OFF SEQUENCE SETTING (PFS) (R03H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Setting Power OFF sequence	0	0	<b>0</b>	<b>0</b>	<b>0</b>	<b>0</b>	<b>0</b>	<b>0</b>	<b>1</b>	<b>1</b>	03H
	0	1	-	-	T_VDS_OFF[1:0]	-	-	-	-	-	00H

**T\_VDS\_OFF[1:0]:** Source to gate power off interval time.

00b: 1 frame (Default)      01b: 2 frames      10b: 3 frames      11b: 4 frame

### (5) POWER ON (PON) (REGISTER: R04H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Turning ON the power	0	0	<b>0</b>	<b>0</b>	<b>0</b>	<b>0</b>	<b>0</b>	<b>1</b>	<b>0</b>	<b>0</b>	04H

After the Power ON command, the driver will be powered ON. Refer to the POWER MANAGEMENT section for the sequence.

This command will turn on booster, controller, regulators, and temperature sensor will be activated for one-time sensing before enabling booster. When all voltages are ready, the BUSY\_N signal will return to high.

### (6) POWER ON MEASURE (PMES) (R05H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
	0	0	<b>0</b>	<b>0</b>	<b>0</b>	<b>0</b>	<b>0</b>	<b>1</b>	<b>0</b>	<b>1</b>	05H

This command enables the internal bandgap, which will be cleared by the next POF.

## (7) BOOSTER SOFT START (BTST) (R06H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Starting data transmission	0	0	0	0	0	0	0	1	1	0	06H
	0	1	BT_PHA7	BT_PHA6	BT_PHA5	BT_PHA4	BT_PHA3	BT_PHA2	BT_PHA1	BT_PHA0	17H
	0	1	BT_PHB7	BT_PHB6	BT_PHB5	BT_PHB4	BT_PHB3	BT_PHB2	BT_PHB1	BT_PHB0	17H
	0	1	-	-	BT_PHC5	BT_PHC4	BT_PHC3	BT_PHC2	BT_PHC1	BT_PHC0	17H

**BTPHA[7:6]:** Soft start period of phase A.

**00b: 10mS**

**01b: 20mS**

**10b: 30mS**

**11b: 40mS**

**BTPHA[5:3]:** Driving strength of phase A

000b: strength 1

100b: strength 5

001b: strength 2

101b: strength 6

**010b: strength 3**

110b: strength 7

011b: strength 4

111b: strength 8 (strongest)

**BTPHA[2:0]:** Minimum OFF time setting of GDR in phase B

000b: 0.27uS

100b: 0.80uS

001b: 0.34uS

101b: 1.54uS

010b: 0.40uS

110b: 3.34uS

011b: 0.54uS

**111b: 6.58uS**

**BTPHB[7:6]:** Soft start period of phase B.

**00b: 10mS**

**01b: 20mS**

**10b: 30mS**

**11b: 40mS**

**BTPHB[5:3]:** Driving strength of phase B

000b: strength 1

100b: strength 5

001b: strength 2

101b: strength 6

**010b: strength 3**

110b: strength 7

011b: strength 4

111b: strength 8 (strongest)

**BTPHB[2:0]:** Minimum OFF time setting of GDR in phase B

000b: 0.27uS

100b: 0.80uS

001b: 0.34uS

101b: 1.54uS

010b: 0.40uS

110b: 3.34uS

011b: 0.54uS

**111b: 6.58uS**

**BTPHC[5:3]:** Driving strength of phase C

000b: strength 1

100b: strength 5

001b: strength 2

101b: strength 6

**010b: strength 3**

110b: strength 7

011b: strength 4

111b: strength 8 (strongest)

**BTPHC[2:0]:** Minimum OFF time setting of GDR in phase C

000b: 0.27uS

100b: 0.80uS

001b: 0.34uS

101b: 1.54uS

010b: 0.40uS

110b: 3.34uS

011b: 0.54uS

**111b: 6.58uS**

## (8) DEEP SLEEP (DSLP) (R07H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Deep Sleep	0	0	0	0	0	0	0	1	1	1	07H
	0	1	1	0	1	0	0	1	0	1	A5H

After this command is transmitted, the chip will enter Deep Sleep Mode to save power. Deep Sleep Mode will return to Standby Mode by hardware reset. The only one parameter is a check code, the command will be executed if check code = 0xA5.

**(9) DATA START TRANSMISSION 1 (DTM1) (R10H)**

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Starting data transmission	0	0	0	0	0	1	0	0	0	0	10H
	0	1	Pixel1	Pixel2	Pixel3	Pixel4	Pixel5	Pixel6	Pixel7	Pixel8	00H
	0	1	:	:	:	:	:	:	:	:	00H
	0	1	Pixel(n-7)	Pixel(n-6)	Pixel(n-5)	Pixel(n-4)	Pixel(n-3)	Pixel(n-2)	Pixel(n-1)	Pixel(n)	00H

This command starts transmitting data and write them into SRAM.

In KW mode, this command writes "OLD" data to SRAM.

In KWR mode, this command writes "B/W" data to SRAM.

In Program mode, this command writes "OTP" data to SRAM for programming.

**(10) DATA STOP (DSP) (R11H)**

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Stopping data transmission	0	0	0	0	0	1	0	0	0	1	11H
	1	1	data_flag	-	-	-	-	-	-	-	00H

Check the completeness of data. If data is complete, start to refresh display.

**Data\_flag:** Data flag of receiving user data.

0: Driver didn't receive all the data.

1: Driver has already received all the one-frame data (DTM1 and DTM2).

After "Data Start" (R10h) or "Data Stop" (R11h) commands and when data\_flag=1, the refreshing of panel starts and BUSY\_N signal will become "0".

**(11) DISPLAY REFRESH (DRF) (R12H)**

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Refreshing the display	0	0	0	0	0	1	0	0	1	0	12H

While user sent this command, driver will refresh display (data/VCOM) according to SRAM data and LUT.

After Display Refresh command, BUSY\_N signal will become "0" and the refreshing of panel starts.

The waiting interval from BUSY\_N falling to the first FLG command must be larger than 200uS.

**(12) DATA START TRANSMISSION 2 (DTM2) (R13H)**

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Starting data transmission	0	0	0	0	0	1	0	0	1	1	13H
	0	1	Pixel1	Pixel2	Pixel3	Pixel4	Pixel5	Pixel6	Pixel7	Pixel8	00H
	0	1	:	:	:	:	:	:	:	:	00H
	0	1	Pixel(n-7)	Pixel(n-6)	Pixel(n-5)	Pixel(n-4)	Pixel(n-3)	Pixel(n-2)	Pixel(n-1)	Pixel(n)	00H

This command starts transmitting data and write them into SRAM.

In KW mode, this command writes "NEW" data to SRAM.

In KWR mode, this command writes "RED" data to SRAM.

## (13) AUTO SEQUENCE (AUTO) (R17H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Auto Sequence	0	0	0	0	0	1	0	1	1	1	17H
	0	1	1	0	1	0	0	1	0	1	A5H

The command can enable the internal sequence to execute several commands continuously. The successive execution can minimize idle time to avoid unnecessary power consumption and reduce the complexity of host's control procedure. The sequence contains several operations, including PON, DRF, POF, DSLP.

AUTO (0x17) + Code(0xA5) = (PON → DRF → POF)

AUTO (0x17) + Code(0xA7) = (PON → DRF → POF → DSLP)

## (14) LUT OPTION (LUTOPT) (R2AH)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
LUT Option	0	0	0	0	1	0	1	0	1	0	2AH
	0	1	-	-							00H
	0	1	-	-		EXS[2:0]		-		DMS[2:0]	00H

This command sets XON and the 2 options of KWR mode's LUT.

**STATE\_XON[5:0]:**

All Gate ON (Each bit controls one state, STATE\_XON [0] for state-1, STATE\_XON [1] for state-2 ....)

00 0000b: no All-Gate-ON

00 0001b: State-1 All-Gate-ON

00 0011b: State-1 and State2 All-Gate-ON

: : :

**DMS[2:0]:** Dummy state position. The option is only available when KW/R=0.

**EXS[1:0]:** Extra state number. The option is only available when KW/R=0.

## (15) PLL CONTROL (PLL) (R30H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Controlling PLL	0	0	0	0	1	1	0	0	0	0	30H
	0	1	-	-	M[2:0]					N[2:0]	3CH

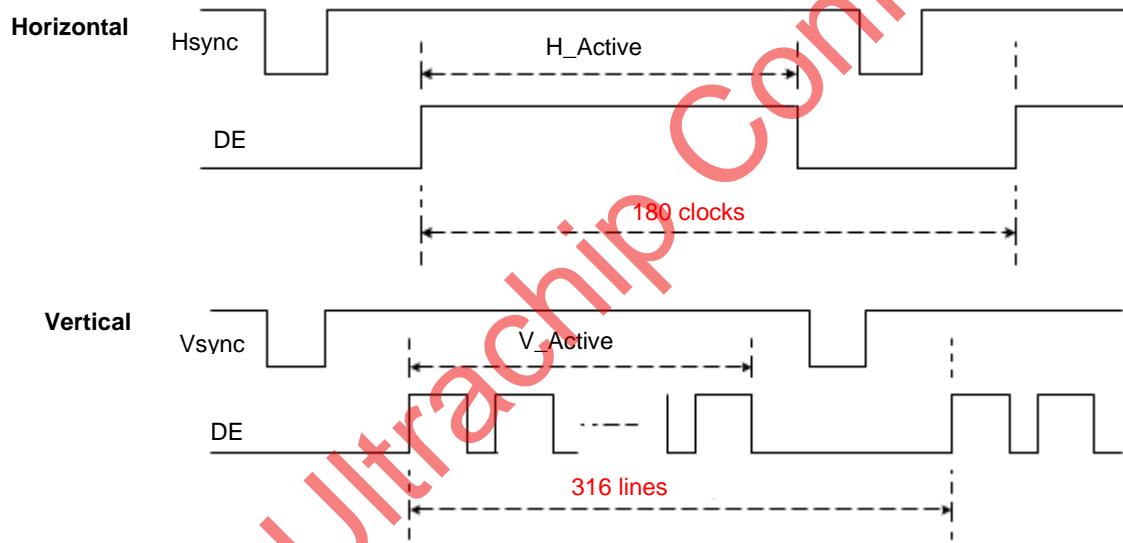
The command controls the PLL clock frequency. The PLL structure must support the following frame rates:

M	N	Frame rate
1	1	29 Hz
	2	14 Hz
	3	10 Hz
	4	7 Hz
	5	6 Hz
	6	5 Hz
	7	4 Hz
2	1	57 Hz
	2	29 Hz
	3	19 Hz
	4	14 Hz
	5	11 Hz
	6	10 Hz
	7	8 Hz

M	N	Frame rate
3	1	86 Hz
	2	43 Hz
	3	29 Hz
	4	21 Hz
	5	17 Hz
	6	14 Hz
	7	12 Hz
4	1	114 Hz
	2	57 Hz
	3	38 Hz
	4	29 Hz
	5	23 Hz
	6	19 Hz
	7	16 Hz

M	N	Frame rate
5	1	150 Hz
	2	72 Hz
	3	48Hz
	4	36 Hz
	5	29 Hz
	6	24 Hz
	7	20 Hz
6	1	171 Hz
	2	86 Hz
	3	57 Hz
	4	43 Hz
	5	34 Hz
	6	29 Hz
	7	24 Hz

M	N	Frame rate
7	1	200 Hz
	2	100 Hz
	3	67 Hz
	4	50 Hz (default)
	5	40 Hz
	6	33 Hz
	7	29 Hz



## (16) TEMPERATURE SENSOR CALIBRATION (TSC) (R40H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Sensing Temperature	0	0	0	1	0	0	0	0	0	0	40H
	1	1	D10/TS7	D9/TS6	D8/TS5	D7/TS4	D6 / TS3	D5 / TS2	D4 / TS1	D3 / TS0	00H
	1	1	D2	D1	D0	-	-	-	-	-	00H

This command enables internal or external temperature sensor, and reads the result.

**TS[7:0]:** When TSE (R41h) is set to 0, this command reads internal temperature sensor value.

**D[10:0]:** When TSE (R41h) is set to 1, this command reads external LM75 temperature sensor value.

TS[7:0]/D[10:3]	Temperature (°C)
1110_0111	-25
1110_1000	-24
1110_1001	-23
1110_1010	-22
1110_1011	-21
1110_1100	-20
1110_1101	-19
1110_1110	-18
1110_1111	-17
1111_0000	-16
1111_0001	-15
1111_0010	-14
1111_0011	-13
1111_0100	-12
1111_0101	-11
1111_0110	-10
1111_0111	-9
1111_1000	-8
1111_1001	-7
1111_1010	-6
1111_1011	-5
1111_1100	-4
1111_1101	-3
1111_1110	-2
1111_1111	-1

TS[7:0]/D[10:3]	Temperature(°C)
0000_0000	0
0000_0001	1
0000_0010	2
0000_0011	3
0000_0100	4
0000_0101	5
0000_0110	6
0000_0111	7
0000_1000	8
0000_1001	9
0000_1010	10
0000_1011	11
0000_1100	12
0000_1101	13
0000_1110	14
0000_1111	15
0001_0000	16
0001_0001	17
0001_0010	18
0001_0011	19
0001_0100	20
0001_0101	21
0001_0110	22
0001_0111	23
0001_1000	24

TS[7:0]/D[10:3]	Temperature(°C)
0001_1001	25
0001_1010	26
0001_1011	27
0001_1100	28
0001_1101	29
0001_1110	30
0001_1111	31
0010_0000	32
0010_0001	33
0010_0010	34
0010_0011	35
0010_0100	36
0010_0101	37
0010_0110	38
0010_0111	39
0010_1000	40
0010_1001	41
0010_1010	42
0010_1011	43
0010_1100	44
0010_1101	45
0010_1110	46
0010_1111	47
0011_0000	48
0011_0001	49

## (17) TEMPERATURE SENSOR ENABLE (TSE) (R41H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Enable Temperature Sensor /Offset	0	0	0	1	0	0	0	0	0	1	41H
	0	1	TSE	-	-	-				TO[3:0]	00H

This command selects Internal or External temperature sensor.

**TSE:** Internal temperature sensor switch

**0: Enable (default)**

1: Disable; using external sensor.

**TO[3:0]:** Temperature offset.

TO[3:0]	Calculation
0000 b	+0 (Default)
0001	+1
0010	+2
0011	+3
0100	+4
0101	+5
0110	+6
0111	+7

TO[3:0]	Calculation
1000	-8
1001	-7
1010	-6
1011	-5
1100	-4
1101	-3
1110	-2
1111	-1

## (18) TEMPERATURE SENSOR WRITE (TSW) (R42H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Write External Temperature Sensor	0	0	0	1	0	0	0	0	1	0	42H
	0	1									00H
	0	1									00H
	0	1									00H

This command writes the temperature sensed by the temperature sensor.

**WATTR[7:6]:** I<sup>2</sup>C Write Byte Number

- 00b : 1 byte (head byte only)
- 01b : 2 bytes (head byte + pointer)
- 10b : 3 bytes (head byte + pointer + 1st parameter)
- 11b : 4 bytes (head byte + pointer + 1st parameter + 2nd parameter)

**WATTR[5:3]:** User-defined address bits (A2, A1, A0)

**WATTR[2:0]:** Pointer setting

**WMSB[7:0]:** MSByte of write-data to external temperature sensor

**WLSB[7:0]:** LSByte of write-data to external temperature sensor

## (19) TEMPERATURE SENSOR READ (TSR) (R43H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Read External Temperature Sensor	0	0	0	1	0	0	0	0	1	1	43H
	1	1									00H
	1	1									00H

This command reads the temperature sensed by the temperature sensor.

**RMSB[7:0]:** MSByte read data from external temperature sensor

**RLSB[7:0]:** LSByte read data from external temperature sensor

## (20) PANEL GLASS CHECK (PBC)

Action	R/W	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Check Panel Glass	W	0	0	1	0	0	0	1	0	0	44H
	R	1	-	-	-	-	-	-	-	-	PSTA 00H

This command is used to enable panel check, and to disable after reading result.

**PSTA:** 0: Panel check fail (panel broken)

1: Panel check pass

## (21) VCOM AND DATA INTERVAL SETTING (CDI) (R50H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Set Interval between VCOM and Data	0	0	0	1	0	1	0	0	0	0	
	0	1	VBD[1:0]		DDX[1:0]		CDI[3:0]				

This command indicates the interval of VCOM and data output. When setting the vertical back porch, the total blanking will be kept (20 Hsync).

**VBD[1:0]:** Border data selection

KWR mode (KW/R=0)

DDX[0]	VBD[1:0]	LUT
0	00	Floating
	01	LUTR
	10	LUTW
	11	LUTB
1 <b>(Default)</b>	00	LUTB
	01	LUTW
	10	LUTR
	11	Floating

KW mode (KW/R=1)

DDX[0]	VBD[1:0]	LUT
0	00	Floating
	01	LUTBW (1 → 0)
	10	LUTWB (0 → 1)
	11	Floating
1 <b>(Default)</b>	00	Floating
	01	LUTWB (1 → 0)
	10	LUTBW (0 → 1)
	11	Floating

**DDX[1:0]:** Data polarity.

Under KWR mode (KW/R=0):

DDX[1] is for RED data.  
DDX[0] is for B/W data,

DDX[1:0]	Data {Red, B/W}	LUT
00	00	LUTW
	01	LUTB
	10	LUTR
	11	LUTR
01 <b>(Default)</b>	00	LUTB
	01	LUTW
	10	LUTR
	11	LUTR

DDX[1:0]	Data {Red, B/W}	LUT
10	00	LUTR
	01	LUTR
	10	LUTW
	11	LUTB
11	00	LUTR
	01	LUTR
	10	LUTB
	11	LUTW

Under KW mode (KW/R=1):

DDX[1]=0 is for KW mode with NEW/OLD,  
DDX[1]=1 is for KW mode without NEW/OLD.

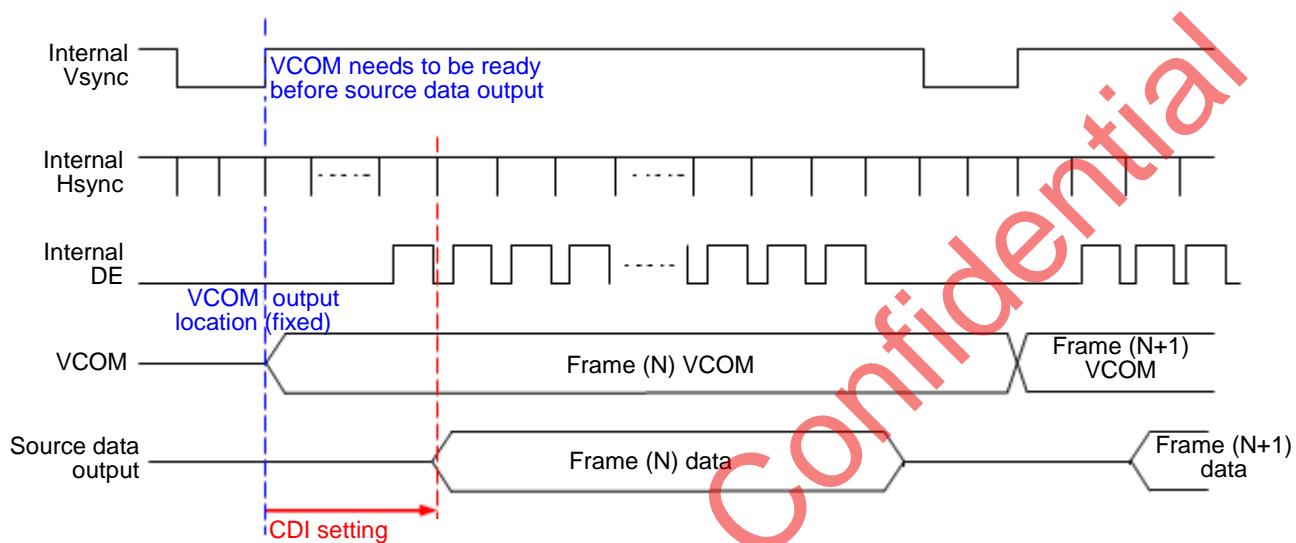
DDX[1:0]	Data {NEW, OLD}	LUT
00	00	LUTWW (0 → 0)
	01	LUTBW (1 → 0)
	10	LUTWB (0 → 1)
	11	LUTBB (1 → 1)
01 <b>(Default)</b>	00	LUTBB (0 → 0)
	01	LUTWB (1 → 0)
	10	LUTBW (0 → 1)
	11	LUTWW (1 → 1)

DDX[1:0]	Data {NEW}	LUT
10	0	LUTBW (1 → 0)
	1	LUTWB (0 → 1)
11	0	LUTWB (1 → 0)
	1	LUTBW (0 → 1)

CDI[3:0]: VCOM and data interval

CDI[3:0]	VCOM and Data Interval
0000 b	17 hsync
0001	16
0010	15
0011	14
0100	13
0101	12
0110	11
<b>0111</b>	<b>10 (Default)</b>

CDI[3:0]	VCOM and Data Interval
1000	9
1001	8
1010	7
1011	6
1100	5
1101	4
1110	3
1111	2



## (22) Low POWER DETECTION (LPD) (R51H)

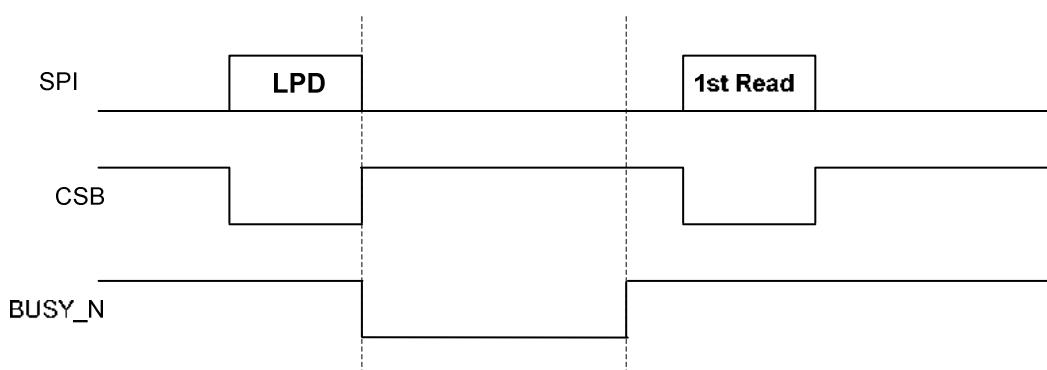
Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0
Detect Low Power	0	0	<b>0</b>	<b>1</b>	<b>0</b>	<b>1</b>	<b>0</b>	<b>0</b>	<b>0</b>	<b>1</b>
	1	1	-	-	-	-	-	-	-	LPD

51h  
01h

This command indicates the input power condition. Host can read this flag to learn the battery condition.

**LPD:** Internal Low Power Detection Flag

- 0: Low power input (VDD<2.5V, selected by LVD\_SEL[1:0] in command LVSEL)
- 1: Normal status (default)



## (23) TCON SETTING (TCON) (R60H)

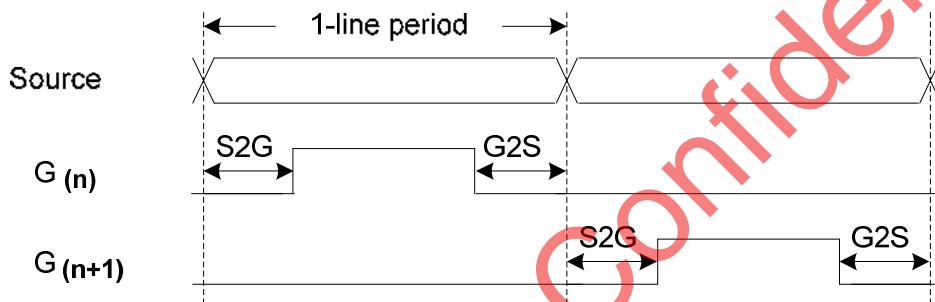
Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Set Gate/Source Non-overlap Period	0	0	0	1	1	0	0	0	0	0	60h
	0	1		S2G[3:0]				G2S[3:0]			22h

This command defines non-overlap period of Gate and Source.

**S2G[3:0] or G2S[3:0]:** Source to Gate / Gate to Source Non-overlap period

S2G[3:0] or G2S[3:0]	Period	S2G[3:0] or G2S[3:0]	Period
0000 b	4	1000 b	36
0001	8	1001	40
<b>0010</b>	<b>12 (Default)</b>	1010	44
0011	16	1011	48
0100	20	1100	52
0101	24	1101	56
0110	28	1110	60
0111	32	1111	64

Period Unit = 660 nS.



## (24) RESOLUTION SETTING (TRES) (R61H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Set Display Resolution	0	0	0	1	1	0	0	0	0	1	61h
	0	1			HRES[7:3]			0	0	0	00h
	0	1	-	-	-	-	-	-	-	VRES[8]	00h
	0	1				VRES[7:0]					00h

This command defines alternative resolution and this setting is of higher priority than the RES[1:0] in R00H (PSR).

**HRES[7:3]:** Horizontal Display Resolution

**VRES[8:0]:** Vertical Display Resolution

Active channel calculation:

Gate: First active gate = G0 (defined by GSST setting, default start gate is G0);  
Last active gate = VRES[8:0] - 1

Source: First active source = S0 (defined by GSST setting, default start source is S0);  
Last active source = HRES[7:3]\*8 - 1

Example: 128 (source) x 272 (gate)

Gate: First active gate = G0 (default start gate),  
Last active gate = 272 - 1 = 271; (VRES[8:0] = 272, G271)

Source: First active source = S0 (default start source),  
Last active source = 16\*8 - 1 = 127; (HRES[7:3]=16, S127)

## (25) GATE/SOURCE START SETTING (GSST) (R65H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Set Gate/Source Start	0	0	0	1	1	0	0	1	0	1	65h
	0	1	HST[7:3]					0	0	0	00h
	0	1	-	-	-	-	-	-	-	VST[8]	00h
	0	1	VST[7:0]								00h

This command defines resolution start gate/source position.

**HST[7:3]:** Horizontal Display Start Position (Source)

**VST[8:0]:** Vertical Display Start Position (Gate)

Example : 128(Source) x 240(Gate)

HST[7:3] = 4 (HST = 4\*8 = 32),

VST[8:0] = 32

Gate: First active gate = G32 (Because HST[7:3] = 4),  
Last active gate = G271

Source: First active source = S32 (Because VST[8:0] = 32),  
Last active source = S159

## (26) REVISION (REV) (R70H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0
Chip Revision	0	0	0	1	1	1	0	0	0	0
	1	1					LUT_REV			
	1	1	-	-	-	-		LUT_REV[3:0]		

The LUT\_REV is read from OTP address = 0x001 / 0x801.

**CHIP\_REV[3:0]:** Chip Revision, fixed at 1101b.

## (27) GET STATUS (FLG) (R71H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0
Read Flags	0	0	0	1	1	1	0	0	0	1
	1	1	-	PTL_flag	I <sup>2</sup> C_ERR	I <sup>2</sup> C_BUSYN	data_flag	PON	POF	BUSY_N

This command reads the IC status.

**PTL\_FLAG:** Partial display status (high: partial mode)

**I<sup>2</sup>C\_ERR:** I<sup>2</sup>C master error status

**I<sup>2</sup>C\_BUSYN:** I<sup>2</sup>C master busy status (low active)

**data\_flag:** Driver has already received all the one frame data

**PON:** Power ON status

**POF:** Power OFF status

**BUSY\_N:** Driver busy status (low active)

## (28) AUTO MEASURE VCOM (AMV) (R80H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0
Automatically measure VCOM	0	0	1	0	0	0	0	0	0	0
	0	1	-	-	AMVT[1:0]	XON	AMVS	AMV	AMVE	

This command reads the IC status.

**AMVT[1:0]:** Auto Measure VCOM Time

00b: 3s

10b: 8s

01b: 5s (default)

11b: 10s

**XON:** All Gate ON of AMV

**0: Gate normally scan during Auto Measure VCOM period. (default)**

1: All Gate ON during Auto Measure VCOM period.

**AMVS:** Source output of AMV

**0: Source output 0V during Auto Measure VCOM period. (default)**

1: Source output VDHR during Auto Measure VCOM period.

**AMV:** Analog signal

**0: Get VCOM value with the VV command (R81h) (default)**

1: Get VCOM value in analog signal. (External analog to digital converter)

**AMVE:** Auto Measure VCOM Enable (/Disable)

**0: No effect (default)**

1: Trigger auto VCOM sensing.



## (31) PARTIAL WINDOW (PTL) (R90H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Set Partial Window	0	0	1	0	0	0	0	0	1	0	90h
	0	1	HRST[7:3]						0	0	00h
	0	1	HRED[7:3]						1	1	07h
	0	1	-	-	-	-	-	-	-	-	00h
	0	1	VRST[7:0]								00h
	0	1	-	-	-	-	-	-	-	-	00h
	0	1	VRED[7:0]								00h
	0	1	-	-	-	-	-	-	-	-	PT_SCAN

This command sets partial window.

**HRST[7:3]:** Horizontal start channel bank. (value 00h~13h)

**HRED[7:3]:** Horizontal end channel bank. (value 00h~13h). HRED must be greater than HRST.

**VRST[8:0]:** Vertical start line. (value 000h~127h)

**VRED[8:0]:** Vertical end line. (value 000h~127h). VRED must be greater than VRST.

**PT\_SCAN:** 0: Gates scan only inside of the partial window.

1: Gates scan both inside and outside of the partial window. (default)

## (32) PARTIAL IN (PTIN) (R91H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Partial In	0	0	1	0	0	1	0	0	0	1	91h

This command makes the display enter partial mode.

## (33) PARTIAL OUT (PTOUT) (R92H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Partial Out	0	0	1	0	0	1	0	0	1	0	92h

This command makes the display exit partial mode and enter normal mode.

## (34) PROGRAM MODE (PGM) (RA0H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Enter Program Mode	0	0	1	0	1	0	0	0	0	0	A0h

After this command is issued, the chip would enter the program mode.

After the programming procedure completed, a hardware reset is necessary for leaving program mode.

## (35) ACTIVE PROGRAM (APG) (RA1H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Active Program OTP	0	0	1	0	1	0	0	0	0	1	A1h

After this command is transmitted, the programming state machine would be activated.

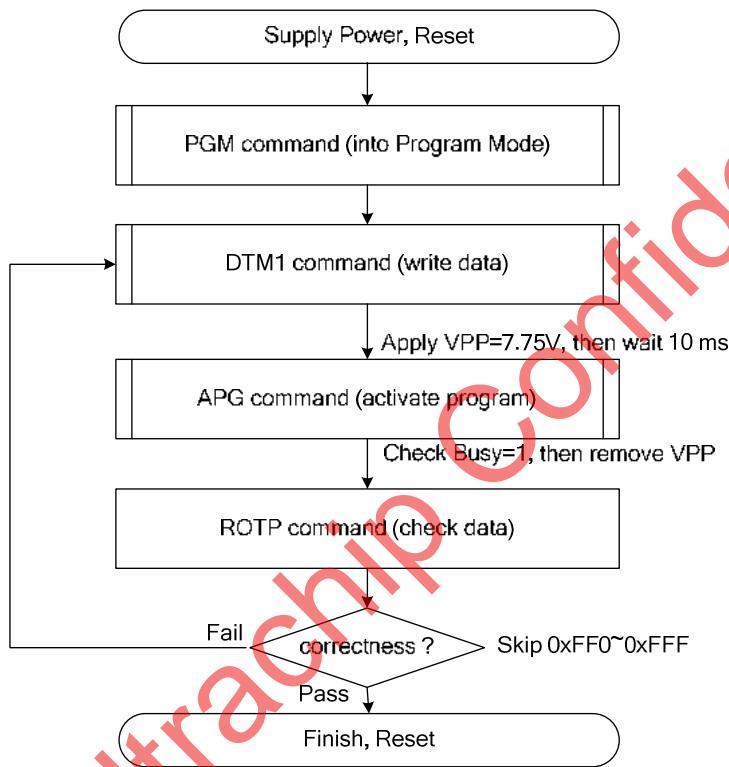
The BUSY\_N flag would fall to 0 until the programming is completed.

## (36) READ OTP DATA (ROTP) (RA2H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Read OTP data for check	0	0	1	0	1	0	0	0	1	0	A2h
	1	1									--
	1	1									--
	1	1									--
	1	1							:		--
	1	1									--
	1	1									--

The command is used for reading the content of OTP for checking the data of programming.

The value of (n) is depending on the amount of programmed data, the max address = 0xFFFF.



The sequence of programming OTP.

## (37) CASCADE SETTING (CCSET) (RE0H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Set Cascade Option	0	0	1	1	1	0	0	0	0	0	E0h
	0	1	-	-	-	-	-	-	-	TSFIX	00h

This command is used for cascade.

**CCEN:** Output clock enable/disable.

**0: Output 0V at CL pin. (default)**

1: Output clock at CL pin for slave chip.

**TSFIX:** Let the value of slave's temperature is same as the master's.

**0: Temperature value is defined by internal temperature sensor / external LM75. (default)**

1: Temperature value is defined by TS\_SET[7:0] registers.

## (38) POWER SAVING (PWS) (RE3H)

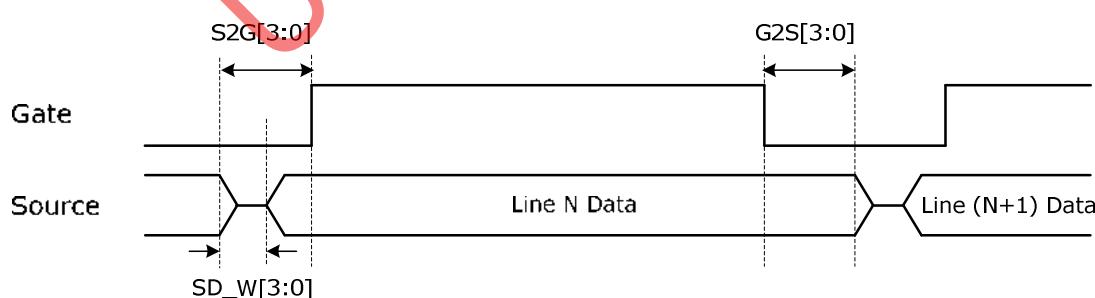
Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Power Saving for VCOM & Source	0	0	1	1	1	0	0	0	1	1	E3h
	0	1		VCOM_W[3:0]				SD_W[3:0]			00h

This command is set for saving power during refreshing period. If the output voltage of VCOM / Source is from negative to positive or from positive to negative, the power saving mechanism will be activated. The active period width is defined by the following two parameters.

**VCOM\_W[3:0]:** VCOM power saving width (unit = line period)



**SD\_W[3:0]:** Source power saving width (unit = 660nS)



## (39) LVD VOLTAGE SELECT (LVSEL) (RE4H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Select LVD Voltage	0	0	1	1	1	0	0	1	0	0	E4h
	0	1	-	-	-	-	-	-	03h	LVD_SEL[1:0]	

LVD\_SEL[1:0]: Low Power Voltage selection

LVD_SEL[1:0]	LVD value
00	< 2.2 V
01	< 2.3 V
10	< 2.4 V
11	< 2.5 V (default)

## (40) FORCE TEMPERATURE (TSSET) (RE5H)

Action	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	
Force Temperature Value for Cascade	0	0	1	1	1	0	0	1	0	1	E5h
	0	1									00h

This command is used for cascade to fix the temperature value of master and slave chip.

## HOST INTERFACES

UC8151 provides 3-wire/4-wire serial interface for command and display data transferred from the MCU. The serial interface supports 8-bit mode. Data can be input/output by clocks while the chip is active (CSB =LOW). While input, data are written in order from MSB at the clock rising edge. When too many parameters are input, the chip accepts only defined parameters, and ignores undefined ones.

BS	Interface	CSB	DC	SCL	SDA
High	3-wire SPI	Available	Fix to GND	Available	Available
Low	4-wire SPI	Available	Available	Available	Available

### 3 wire SPI format

Data / Command is recognized with the first bit transferred. Data are transferred in the unit of 9 bits. To prevent malfunction due to noise, it is recommended to set the CSB signal to HIGH every 9 bits. (The serial counter is reset at the rising edge of the CSB signal.)

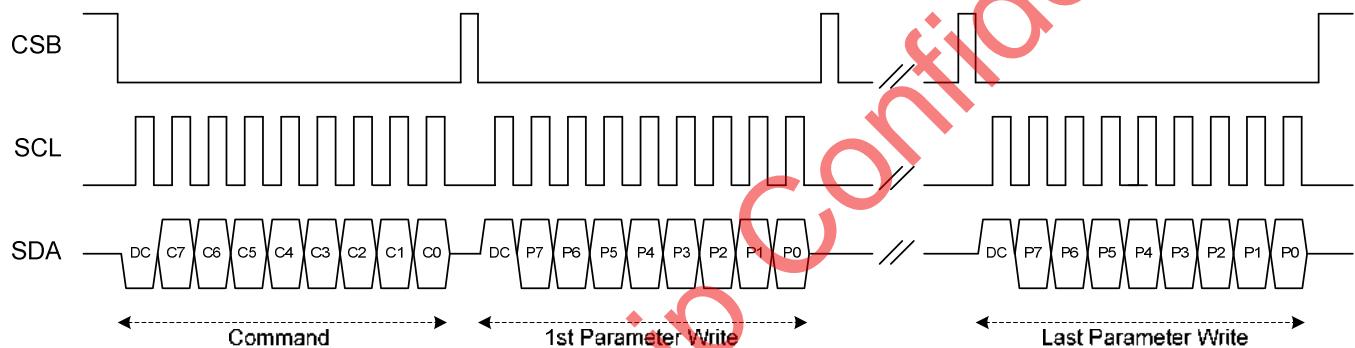


Figure: 3-wire SPI write operation

The MSB bit of data will be output at SDA pin after the 1st SCL falling edge, if the 1st input data at SDA is high. Only in the case of OTP data read, the 1st packet of output data are dummy data.

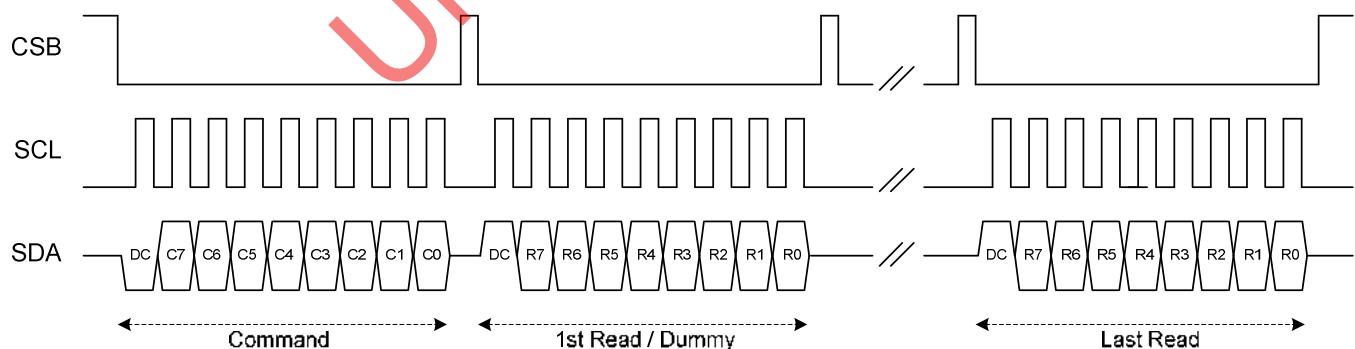
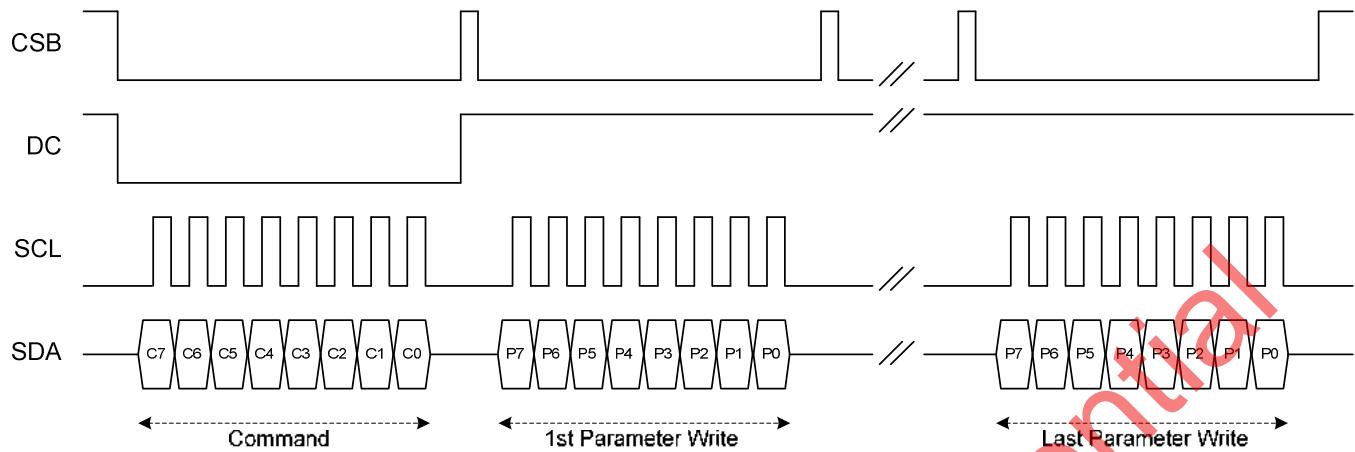


Figure: 3-wire SPI read operation

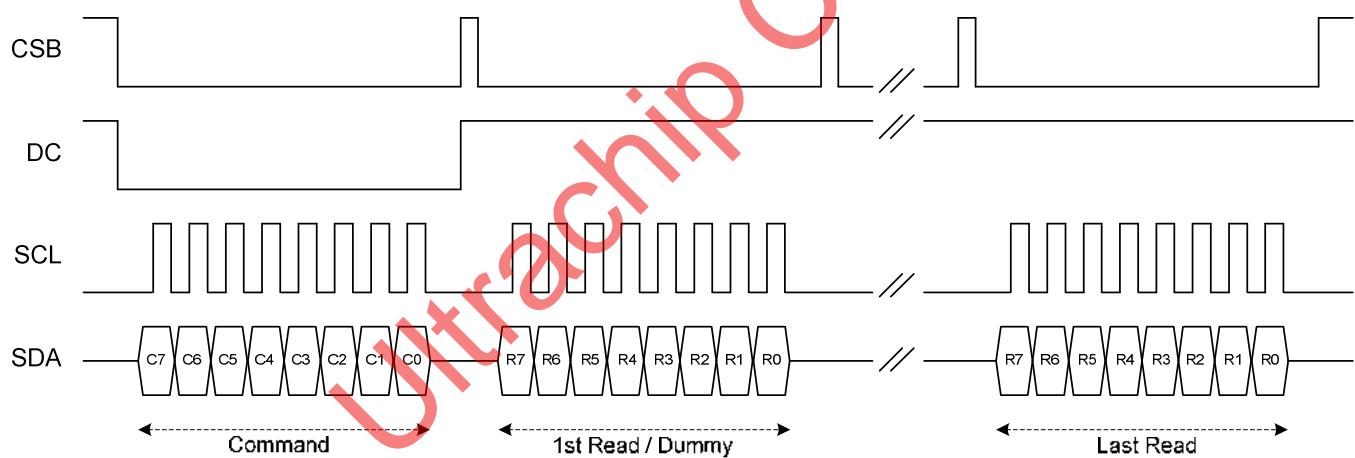
**4 wire SPI format**

Data / Command is recognized with DC pin. Data are transferred in the unit of 8 bits. To prevent malfunction due to noise, it is recommended to set the CSB signal to HIGH every 8 bits. (The serial counter is reset at the rising edge of the CSB signal.)



**Figure:** 4-wire SPI write operation

The MSB bit of data will be output at SDA pin after the CSB falling edge, if DC pin is High. Only in the case of OTP data read, the 1st packet of output data are dummy data.

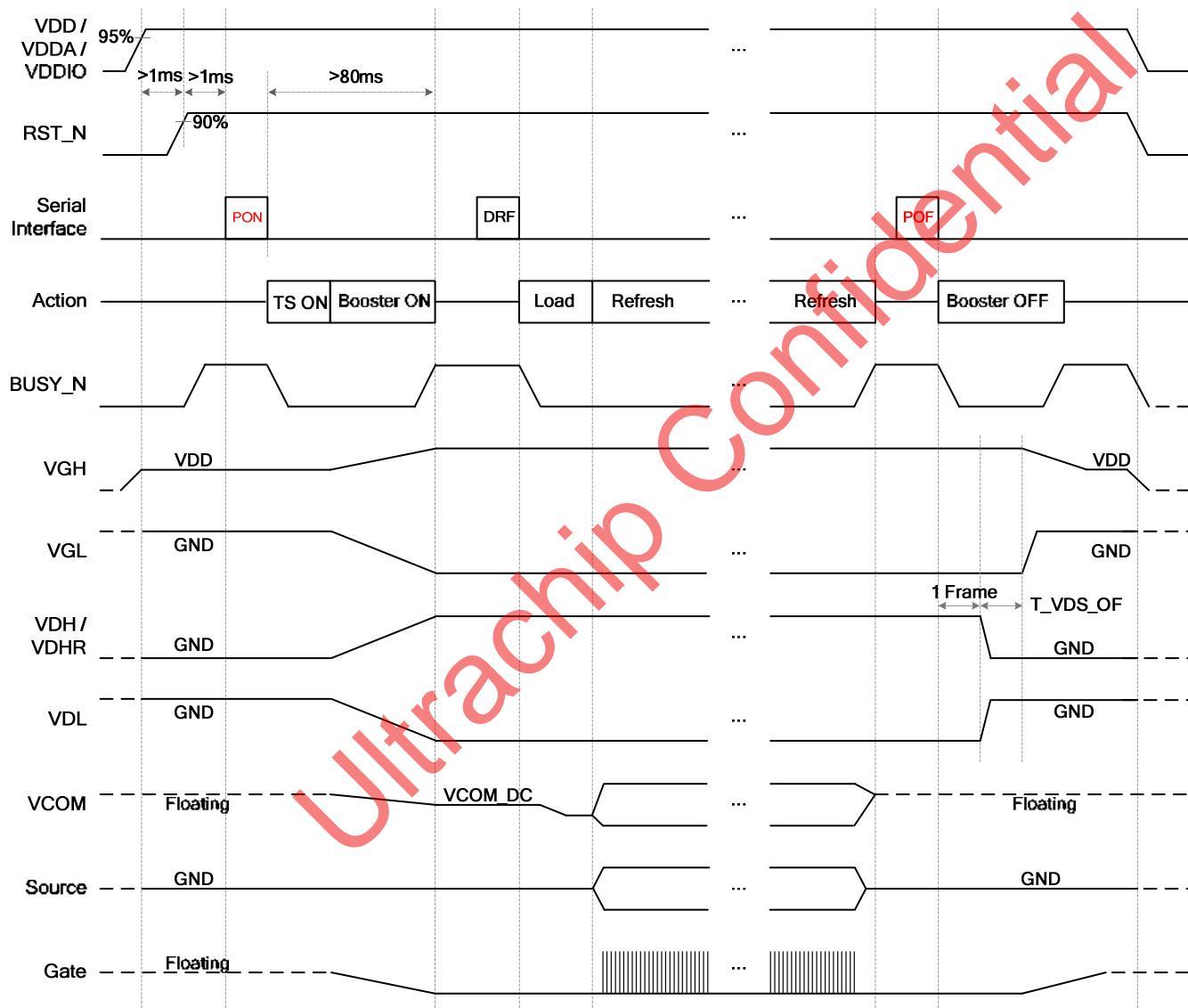


**Figure:** 4-wire SPI read operation

## POWER MANAGEMENT

### Power ON/OFF Sequence

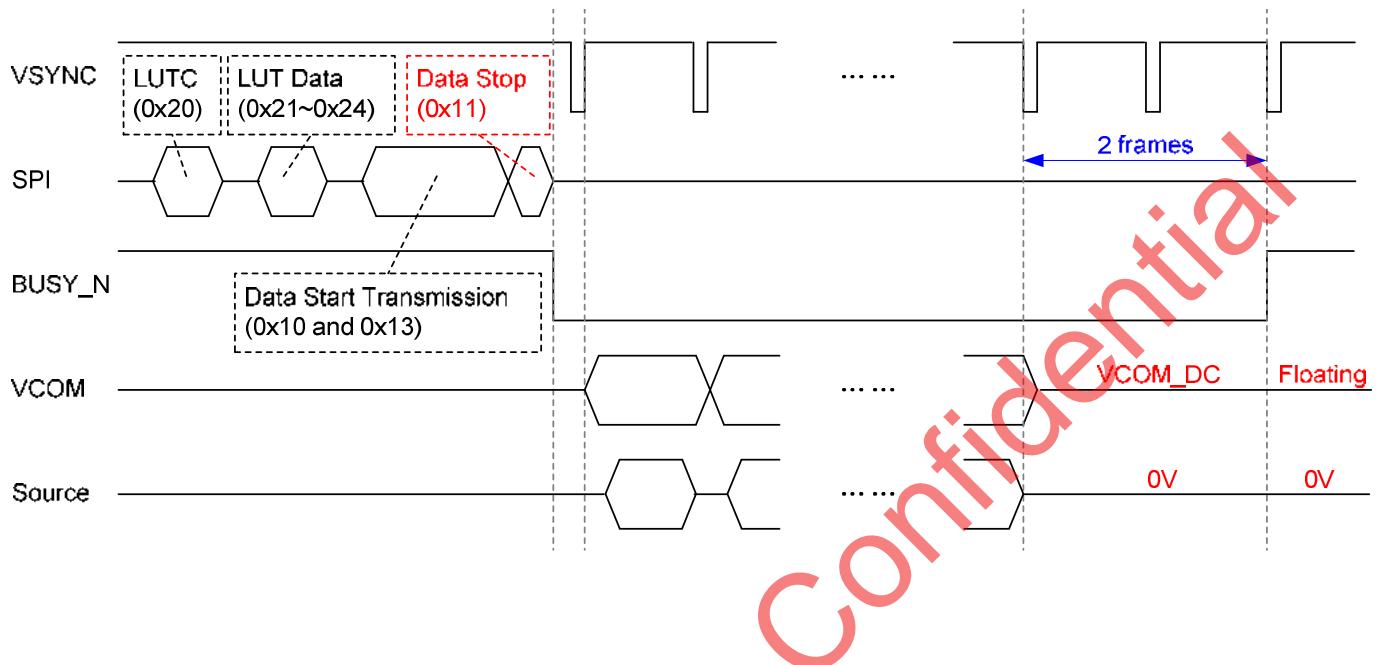
1. Temperature sensor will be activated automatically for one-time sensing before enabling booster.
2. After refreshing display, VCOM will be set to floating automatically.
3. In OTP mode (REG=0), the LUT in OTP will be copied to register automatically after the DSP/DRF command.
4. After RST\_N rising, the waiting time for internal initial processing, greater than 1mS, is necessary. Any commands transmitted to chip during this time will be ignored.



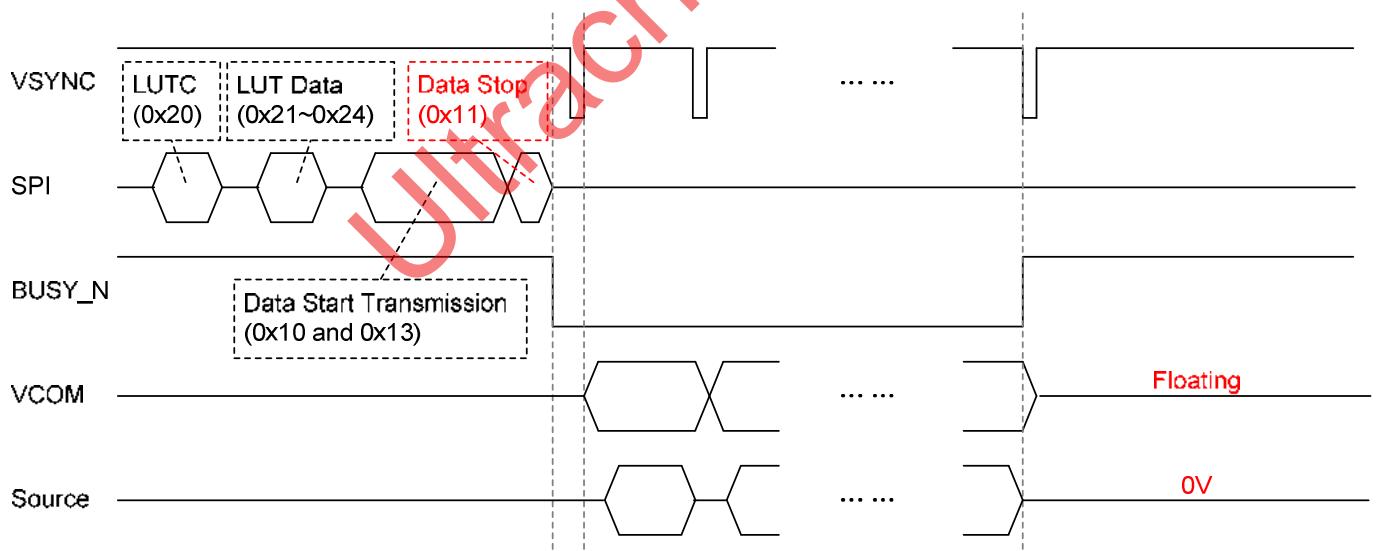
**Data Transmission Waveform**

**Example 1:** After 3 cases, the driver will send 2 frame VCOM and data to 0 V.

1. All 7 LUT states complete.
2. meet the state whose Times to Repeat =0
3. meet the state whose all Number of Frames =0



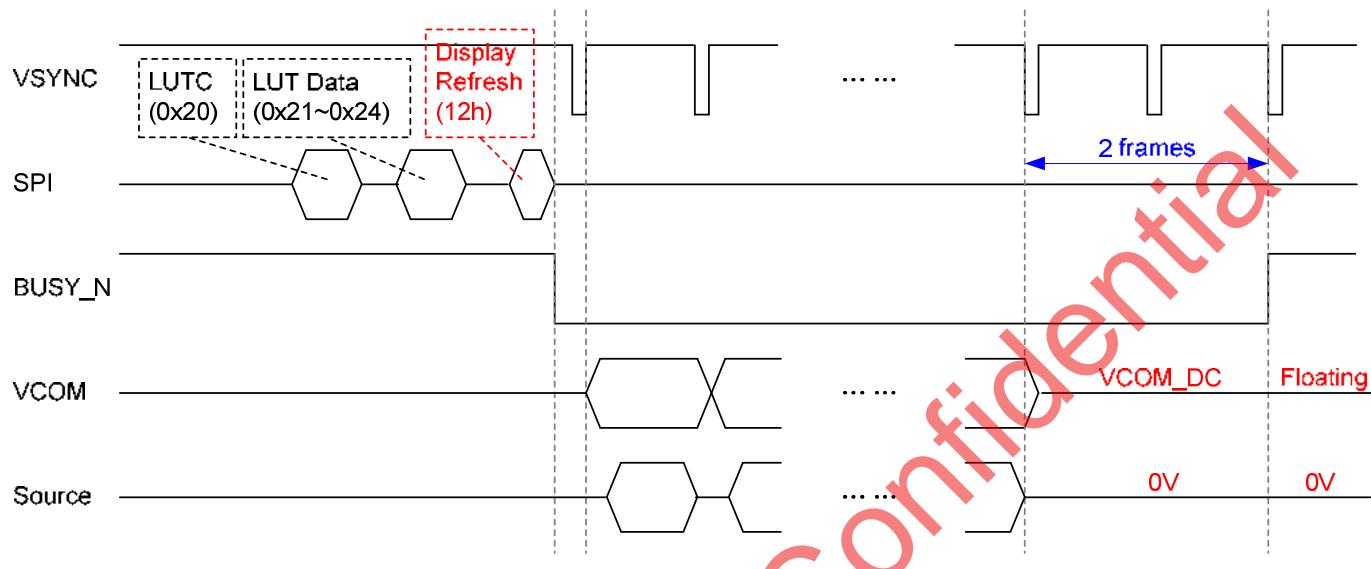
**Example2:** While level selection in LUT (LUTC only) is "1111\_1111b", the driver will float VCOM.



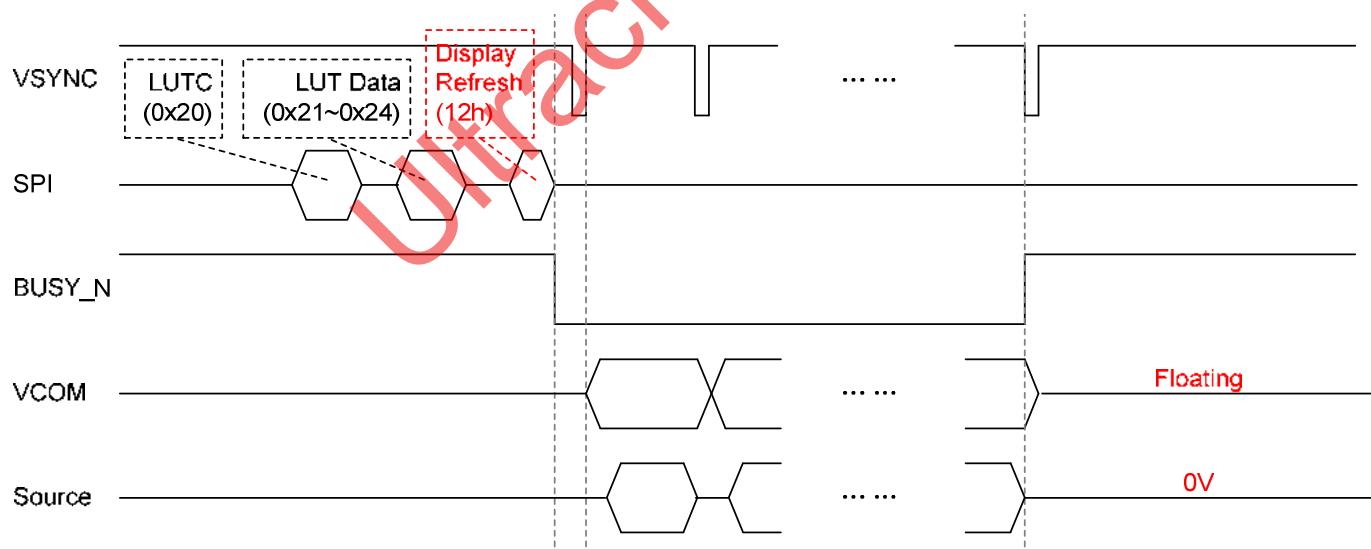
**Display Refresh Waveform**

**Example 1:** After three cases, the driver will send 2 frames VCOM and data to 0 V.

1. All 7 LUT states complete.
2. meet the state whose Times to Repeat = 0
3. meet the state whose all Number of Frames = 0



**Example2:** While level selection in LUT (LUTC only) is "1111\_1111b", the driver will float VCOM.



**BUSY\_N Signal**

Commands, except reading command, are restricted by refreshing display (DRF / DSP) as listed in the following table.

BUSY\_N is used to represent the status of internal action. Commands activating internal operation or calculation will cause BUSY\_N falling to LOW. After actions completed, BUSY\_N will return to HIGH.

Command	Refresh Restriction	BUSY_N flag
PSR	X	No action
PWR	X	No action
POF	X	Flag
PFS	X	No action
PON	X	Flag
PMES	X	Flag
BTST	X	No action
DSLP	X	Flag
AUTO	X	Flag
DTM1	X	No action
DSP	X	Flag
DRF	X	Flag
DTM2	X	No action
LUTC	X	No action
LUTWW	X	No action
LUTWB/LUTW	X	No action
LUTBW/LUTR	X	No action
LUTBB/LUTB	X	No action
LUTOPT	X	No action
PLL	X	No action
TSC	X	Flag
TSE	X	No action
TSW	X	No action
TSR	X	No action
PBC	X	No action
CDI	X	No action
LPD	X	Flag
TCON	X	No action
TRES	X	No action
GSST	X	No action
REV	V	No action
FLG	V	No action
AMV	X	Flag
VV	V	No action
VDCS	X	No action
PTL	X	No action
PTIN	X	No action
PTOUT	X	No action
PGM	X	No action
APG	X	Flag
ROTP	X	No action
CCSET	X	No action
PWS	X	No action
LVSEL	X	No action
TSSET	X	No action

V: Accepted, X: Ignored

## TEMPERATURE RANGE

The temperature selection mechanism consists of a less-than-or-equal-to operator and 9 temperature boundary settings (TBx) to determine 10 temperature ranges. The sequence of mechanism is from TB0 to TB8, as shown below. If less than 10 tempearture ranges are used, the last TBx must be set to 0x7F to end the mechanism.

Procedure Order	Comparison Condition	Action & Segment Selection
1-0. Read 0x000	Content = 0xA5 ?	Yes: Jump to Procedure 2 (Bank0), No: Jump to Procedure 1-1
1-1, Read 0x800	Content = 0xA5 ?	Yes: Jump to Procedure 2 (Bank1), No: Stop Refresh
2. Read 0x002 / 0x802	Real Temperature $\leq$ TB0	Use TR0's table & setting, exit
3. Read 0x003 / 0x803	Real Temperature $\leq$ TB1	Use TR1's table & setting, exit
4. Read 0x004 / 0x804	Real Temperature $\leq$ TB2	Use TR2's table & setting, exit
5. Read 0x005 / 0x805	Real Temperature $\leq$ TB3	Use TR3's table & setting, exit
6. Read 0x006 / 0x806	Real Temperature $\leq$ TB4	Use TR4's table & setting, exit
7. Read 0x007 / 0x807	Real Temperature $\leq$ TB5	Use TR5's table & setting, exit
8. Read 0x008 / 0x808	Real Temperature $\leq$ TB6	Use TR6's table & setting, exit
9. Read 0x009 / 0x809	Real Temperature $\leq$ TB7	Use TR7's table & setting, exit
10. Read 0x00A / 0x80A	Real Temperature $\leq$ TB8	Use TR8's table & setting, exit
11. Other	Real Temperature $>$ TB8	Use TR9's table & setting, finish

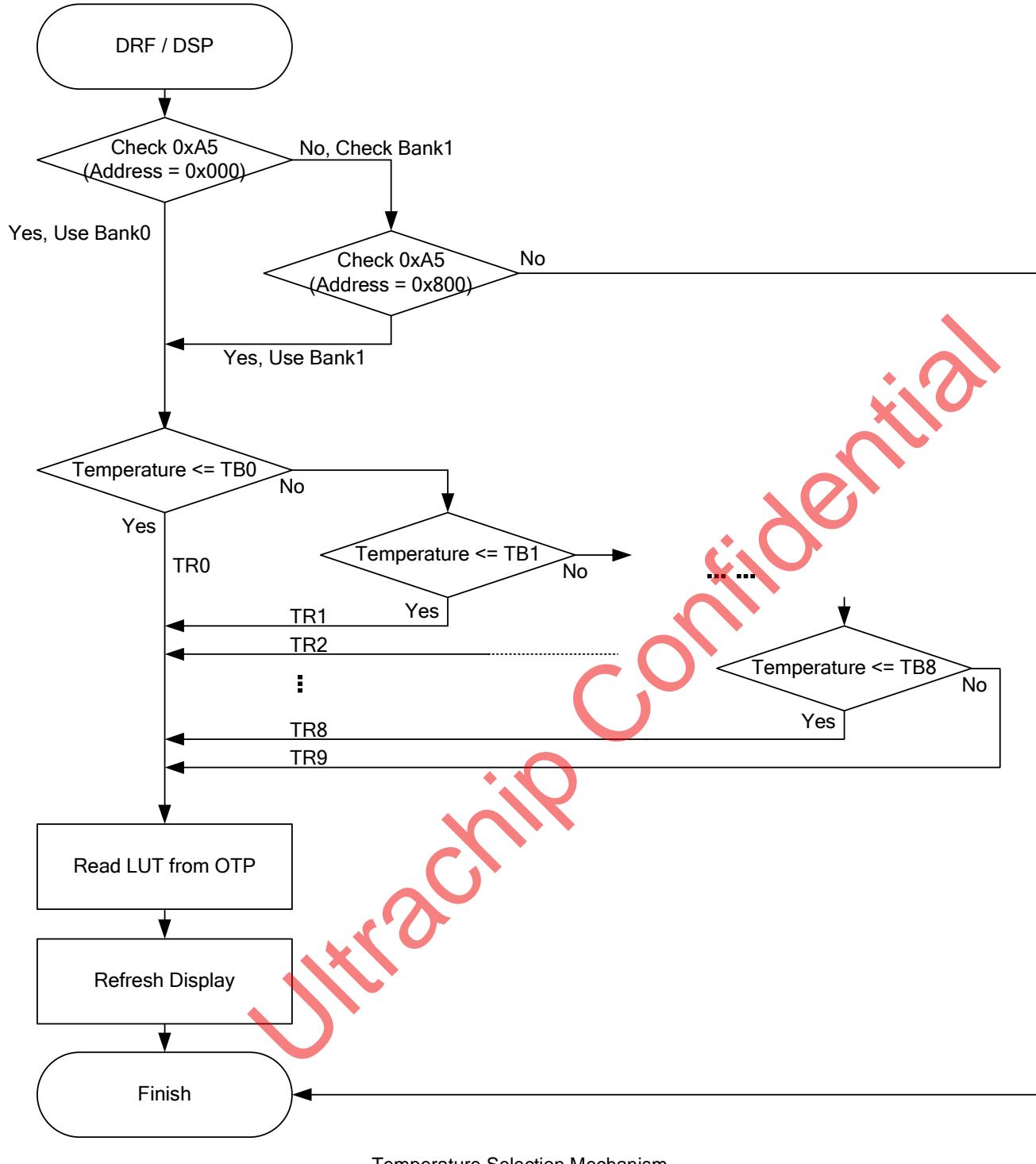
**\*Note:**

- (1) TRx's content is defined in "LUT FORMAT IN OTP" section.

Example:

- If temperature = -20 °C, TR0 is selected.
- If temperature = -10 °C, TR1 is selected.
- If temperature = 0 °C, TR2 is selected.
- If temperature = 20 °C, TR4 is selected.
- If temperature = 40 °C, TR5 is selected.
- If temperature > 40 °C, TR5 is selected.

OTP Address	Content	
002h	0xF1	(-15 °C)
003h	0xFB	( -5 °C)
004h	0x00	( 0 °C)
005h	0x0A	( 10 °C)
006h	0x1E	( 30 °C)
007h	0x7F	-



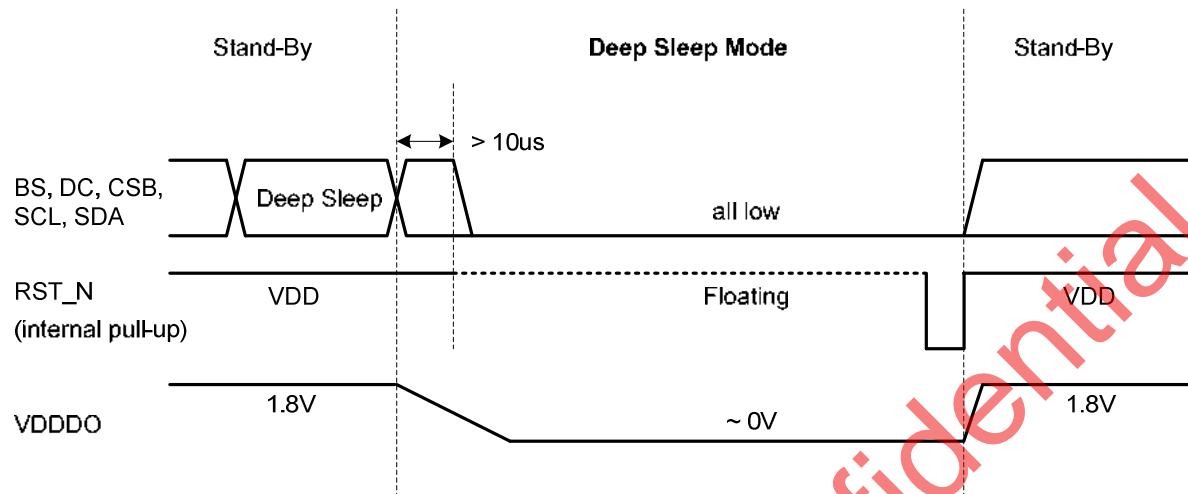
**COMMAND DEFAULT SETTING**

This function can modify the default value of command registers by the OTP content between address 0x00B~0x01D (or 0x80B~0x81D). The data of address 0x00B (or 0x80B) is the enable key of the function. Changing default value function is used to reduce the initial code length executed by the microcontroller.

Address (Hex)	D7	D6	D5	D4	D3	D2	D1	D0	Command	Registers	Original
0x00B	#	#	#	#	#	#	#	#	Check Code	0xA5 (Enable Key)	--
0x00C	#	#	#	#	#	#	--	--	PSR	RES[1:0], REG, KW/R, UD, SHL	0x0F
0x00D	--	--	#	#	--	--	--	--	PFS	T_VDS_OF[1:0]	0x00
0x00E	#	#	#	#	#	#	#	#	BTST	BT_PHA[7:0]	0x17
0x00F	#	#	#	#	#	#	#	#		BT_PHB[7:0]	0x17
0x010	--	--	#	#	#	#	#	#		BT_PHC[5:0]	0x17
0x011	#	--	--	--	#	#	#	#	TSE	TSE, TO[3:0]	0x00
0x012	#	#	#	#	#	#	#	#	CDI	VBD[1:0], DDX[1:0], CDI[3:0]	0xD7
0x013	#	#	#	#	#	#	#	#	TCON	S2G[3:0], G2S[3:0]	0x22
0x014	#	#	#	#	#	#	#	#	TRES	HRES[7:3]	0x00
0x015	--	--	--	--	--	--	--	#		VRES[8:0]	0x00
0x016	#	#	#	#	#	#	#	#			0x00
0x017	#	#	#	#	#	#	#	#	GSST	HST[7:3]	0x00
0x018	--	--	--	--	--	--	--	#		VST[8:0]	0x00
0x019	#	#	#	#	#	#	#	#			0x00
0x01A	--	--	--	--	--	--	#	--	CCSET	TSFIX	0x00
0x01B	#	#	#	#	#	#	#	#	PWS	VCOM_W[3:0], SD_W[3:0]	0x00
0x01C	--	--	--	--	--	--	#	#	LVSEL	LVD_SEL[1:0]	0x03
0x01D	#	#	#	#	#	#	#	#	TSSET	TS_SET[7:0]	0x00

## DEEP SLEEP MODE

After deep sleep command (R07H) is transmitted, UC8151 enter "Deep Sleep Mode", and leaves by RST\_N falling. In "Deep Sleep Mode", the control signals are recommended tied to 0v to avoid IO leakage current. And the die must be keep away from light which causes photoelectric effect to make internal nodes unstable.



## PANEL BREAK CHECK

The panel break check (PBC) function is accomplished by testing the connection of the ITO along panel edge. If the panel is broken, the loop ITO may be cut off. The connection check is judged by signal transmission from CHKG0 to CHKG1.

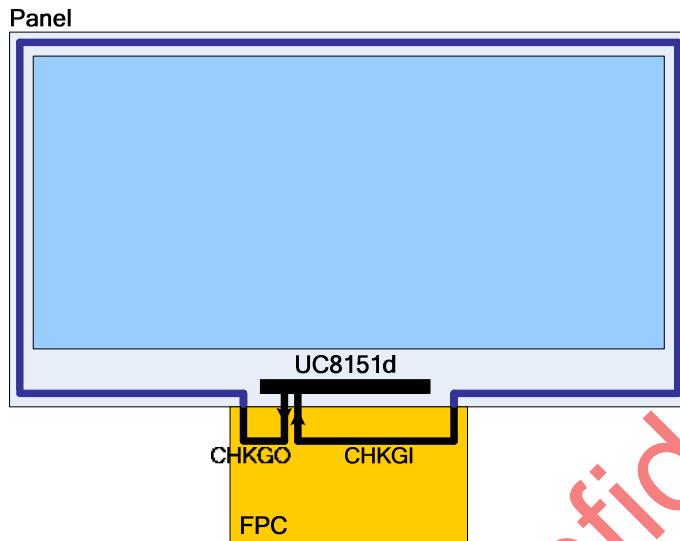


Figure: Panel break check layout example

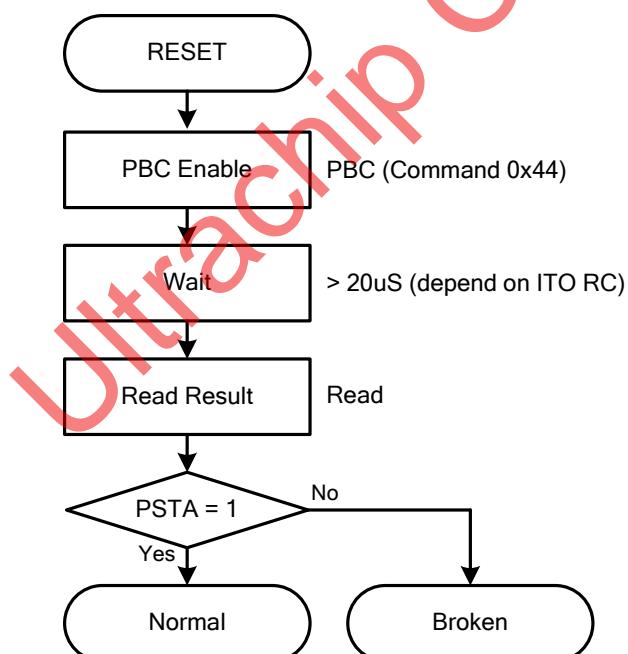
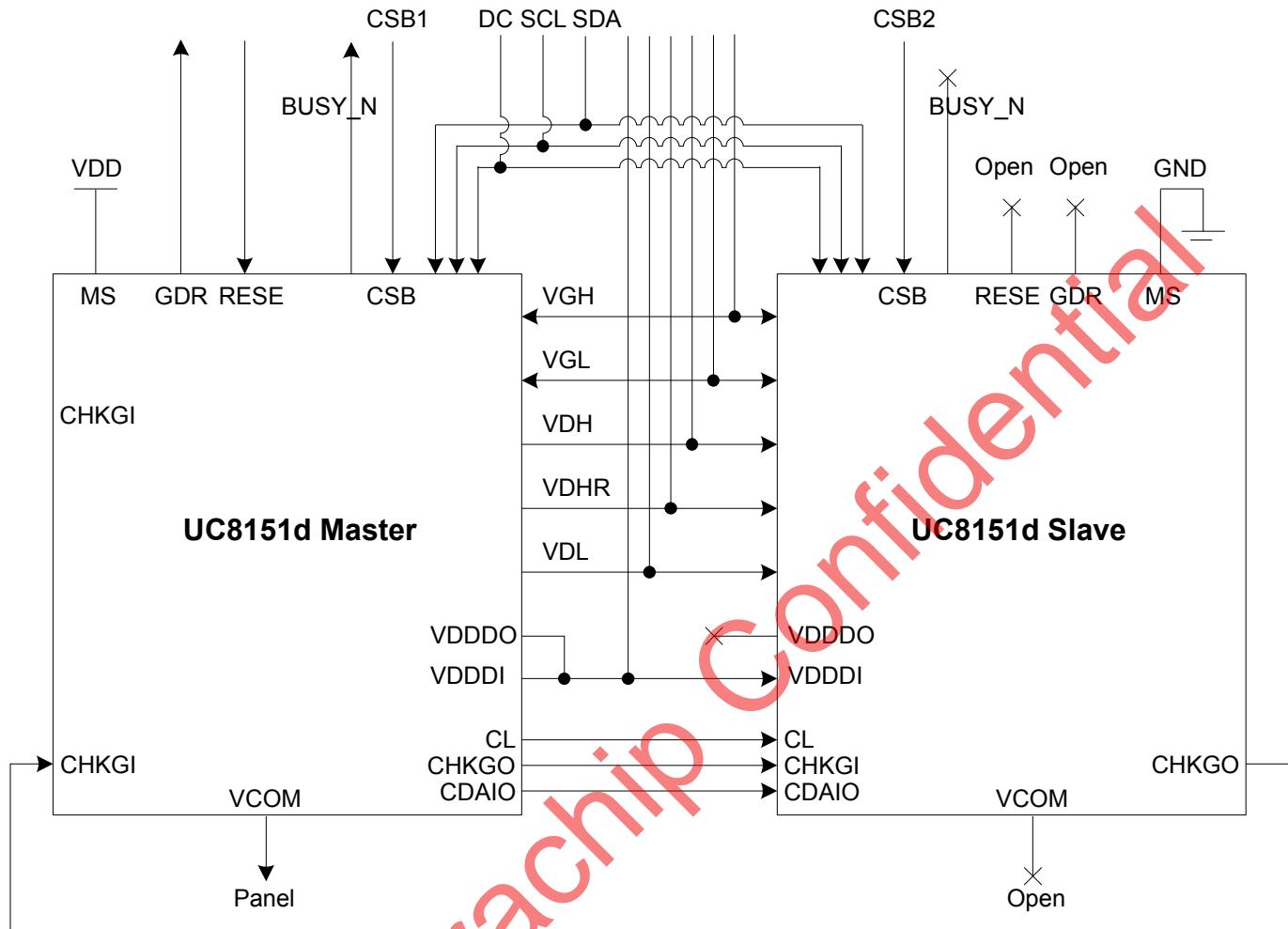


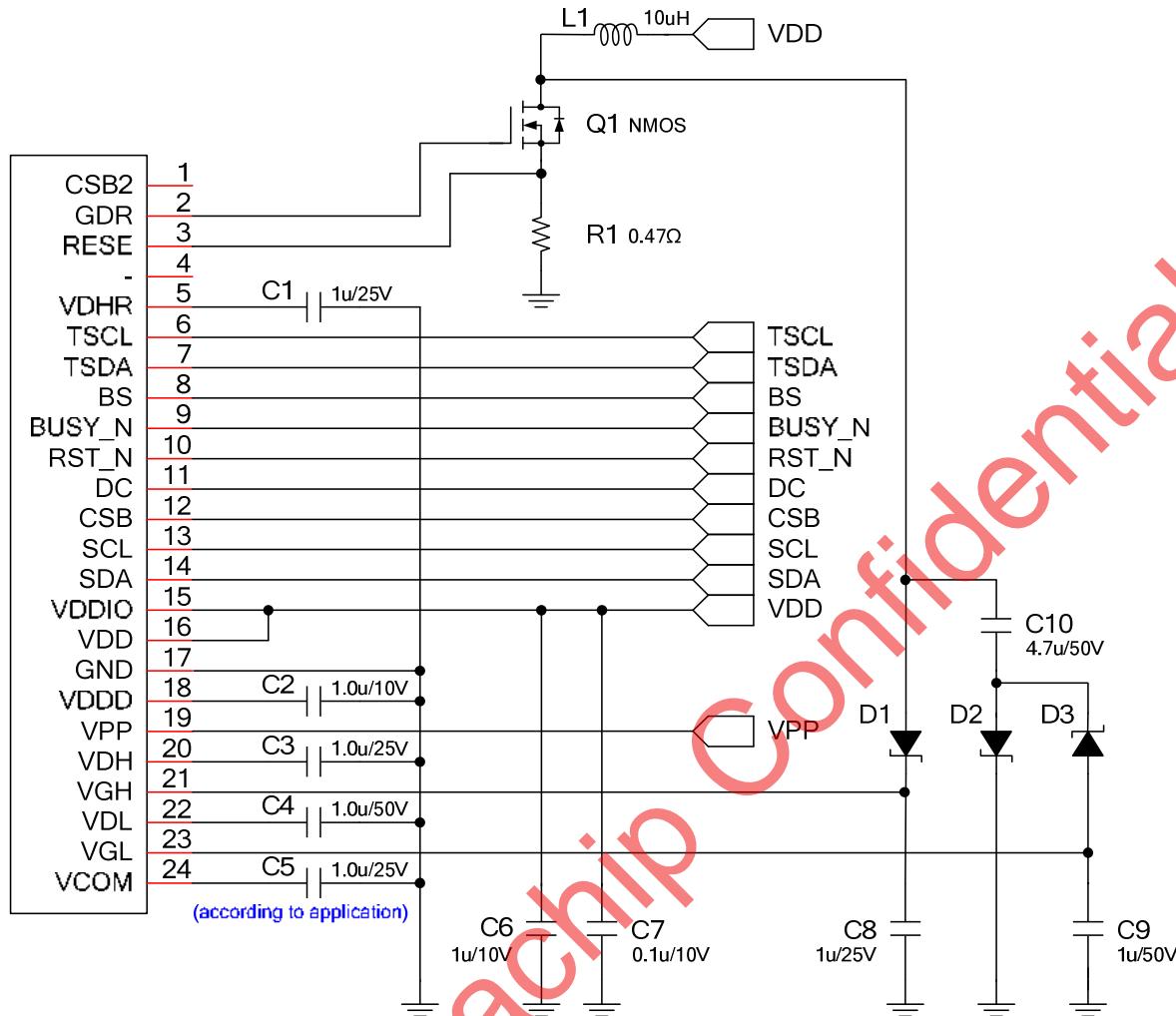
Figure: Panel Break Check (PBC) Sequence

## CASCADE APPLICATION CIRCUIT



All commands sent to **Master** must be also sent to **Slave** except for data writing (DTM1 and DTM2). The display data must be separated to two parts, one is for **Master** and another is for **Slave**. They are transmitted to **Master** and **Slave** individually by using CSB1 and CSB2.

## BOOSTER APPLICATION CIRCUIT



## Recommended Device

1. Switch MOS NMOS: Vishay Si1308EDL ( $V_{DS} > 20V$ ,  $I_D > 500mA$ ,  $V_{GS(th)} < 1.5V$ ,  $C_{iss} < 200pF$ ,  $R_{ds(on)} < 400m\Omega$ )
2. Schottky Diode: OnSemi MBR0530 ( $V_R > 20V$ ,  $I_F > 500mA$ ,  $I_R < 1mA$  @  $V_R=15V$ ,  $T_a=100^\circ C$ )

## Recommended Resistor

Item	Pins	Resistance
Powers	VDD, VDDA, VDDIO, GND, GNDA, VDM	< 10 Ω
Boosters	VGL, VGH, GDR, RESE	< 10 Ω
Regulators	VDH, VDL, VDHR, VCOM, VDDD, VDDDO	< 10 Ω
Logics	MS, BS, CSB, SCL, SDA, GDR, etc.	< 50 Ω
OTP	VPP	< 20 Ω

**ABSOLUTE MAXIMUM RATINGS**

Signal	Item	Min	Max.	Unit
VDD, VDDIO, VDDA	Logic Supply voltage	-0.3	+6.0	V
VPP	OTP programming voltage	-0.3	+8.0	V
VI	Digital input range	-0.3	VDDIO+0.3	V
VGH-VGL	Supply range	-	+44.0	V
<b>Source</b>				
VDH	Analog supply voltage – positive	+16		V
VDL	Analog supply voltage -- negative	-16		V
VDHR	Analog supply voltage – positive	+16		V
<b>Gate</b>				
VGH	Analog supply voltage – positive	-0.3	+22	V
VGL	Analog supply voltage -- negative	-22	0.3	V
IVGH	Input rush current for VGH	(TBD)	(TBD)	mA
IVGL	Input rush current for VGL	(TBD)	(TBD)	mA
TSTG	Storage temperature range	-55	+125	°C

**Warning:**

If ICs are stressed beyond those listed above "absolute maximum ratings", they may be permanently destroyed. These are stress ratings only, and functional operation of the device at these or any other condition beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute maximum rated conditions for extended periods may affect device reliability.

**DC CHARACTERISTICS**

Symbol	Parameter	Conditions	MIN.	TYP.	MAX.	Unit
VDDIO	IO supply voltage		2.3	3.3	3.6	V
VDD	Supply voltage		2.3	3.3	3.6	V
VDDA	DCDC driver supply voltage		2.3	3.3	3.6	V
VIL	LOW Level input voltage	Digital input pins	0	--	0.3xVDD	V
VIH	HIGH Level input voltage	Digital input pins	0.7xVDDIO	--	VDDIO	V
VOH	HIGH Level output voltage	Digital input pins, IOH=400uA	VDDIO-0.4	--	--	V
VOL	LOW Level Output voltage	Digital input pins, IOL=-400uA	0	--	0.4	V
IIN	Input leakage current	Digital input pins except pull-up, pull-down pin	-1	--	1	uA
RIN	Pull-up/down impedance			200		KΩ
Top	Operating temperature		-30		85	°C
dVGH	VGH Supply voltage dev		-400	0	+400	mV
VGH-VGL	Voltage Range of VGH - VGL		--		40	V
dVDH	Supply voltage dev		-200	0	+200	mV
dVDL	Supply voltage dev		-200	0	+200	mV
dVDHR	Supply voltage dev		-200	0	+200	mV
dVCOM	Supply voltage dev		-200	0	+200	mV
RON	Driver Output Resistance	For source driver, TOP=25°C, VOUT = ±15V		16.0	38.4	KΩ
		For gate driver, TOP=25°C, VOUT = ±20V		4.0	8	

VDD=VDDA=VDDIO=3.0V, TOP=25.0 °C

Symbol	Parameter	Conditions	MIN.	TYP.	MAX.	Unit
IVDD	Digital deep sleep current	VDDD OFF	--	0.3	0.5	uA
	Digital stand-by current	All stopped	--	8.2	10.0	uA
	Digital operating current		--	--	0.1	mA
IVDDIO	IO deep sleep current	VDDD OFF	--	0.1	0.3	uA
	IO stand-by current	Booster OFF	--	2.5	4.0	uA
	IO operating current	No load	--	--	0.1	mA
IVDDA	DCDC deep sleep current	VDDD OFF	--	0.1	0.3	uA
	DCDC stand-by current	Booster OFF	--	15.5	20.0	uA
	DCDC operating current	Source output VDH/VDL, Duty=0.5, Period =126us VCOM DC No load	--	--	4.0	mA
		Source output VDH/VDL, Duty=0.5, Period =126us, VCOM DC External cap: 415pF, NMOS=340pF	--	--	20.0	

## AC CHARACTERISTICS

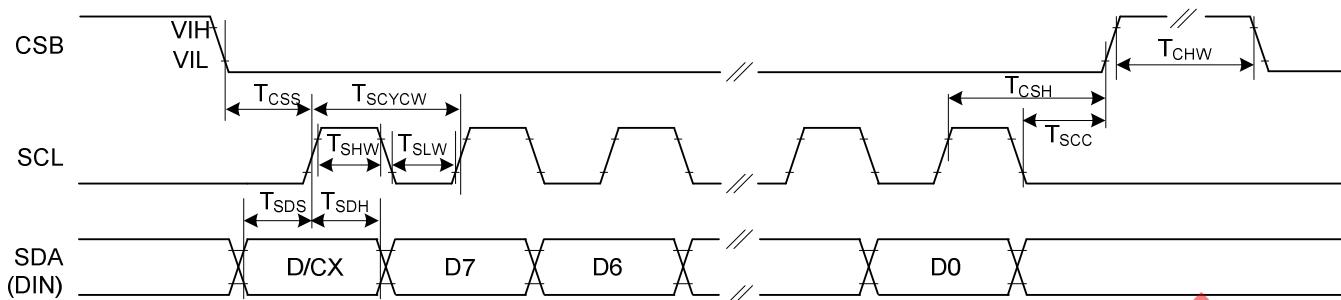


Figure: 3-wire Serial Interface Characteristics (Write mode)

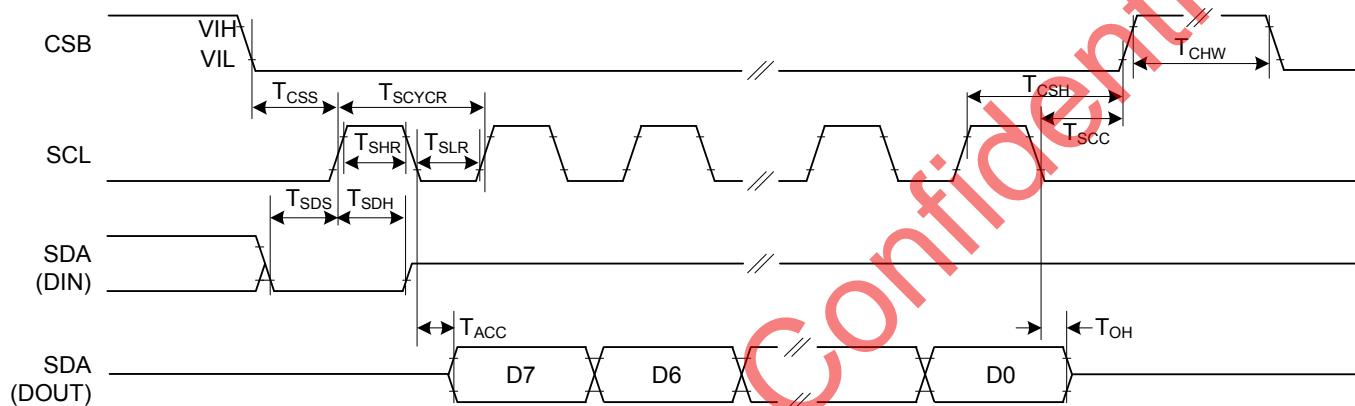


Figure: 3-wire Serial Interface Characteristics (Read mode)

Symbol	Signal / Parameter	Conditions	Min.	Typ.	Max.	Unit
$T_{CSS}$	CSB	Chip select setup time	60			ns
$T_{CSH}$		Chip select hold time	65			ns
$T_{SCC}$		Chip select setup time	20			ns
$T_{CHW}$		Chip select setup time	40			ns
$T_{SCYCW}$	SCL	Serial clock cycle (Write)	100			ns
$T_{SHW}$		SCL "H" pulse width (Write)	35			ns
$T_{SLW}$		SCL "L" pulse width (Write)	35			ns
$T_{SCYCR}$		Serial clock cycle (Read)	150			ns
$T_{SHR}$		SCL "H" pulse width (Read)	60			ns
$T_{SLR}$		SCL "L" pulse width (Read)	60			ns
$T_{SDS}$	SDA (DIN)	Data setup time	30			ns
$T_{SDH}$		Data hold time	30			ns
$T_{ACC}$	SDA (DOUT)	Access time			50	ns
$T_{OH}$		Output disable time	15			ns

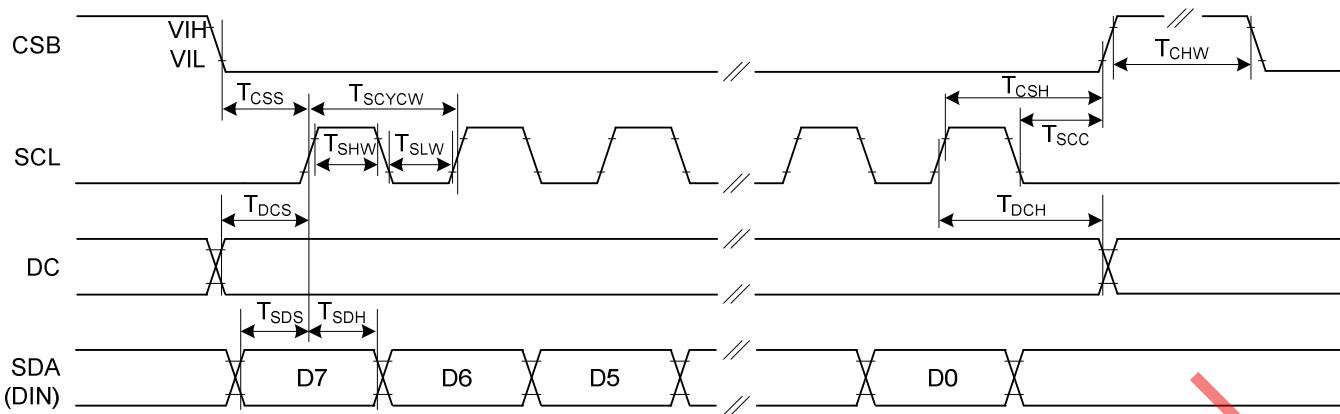


Figure: 4-wire Serial Interface Characteristics (Write mode)

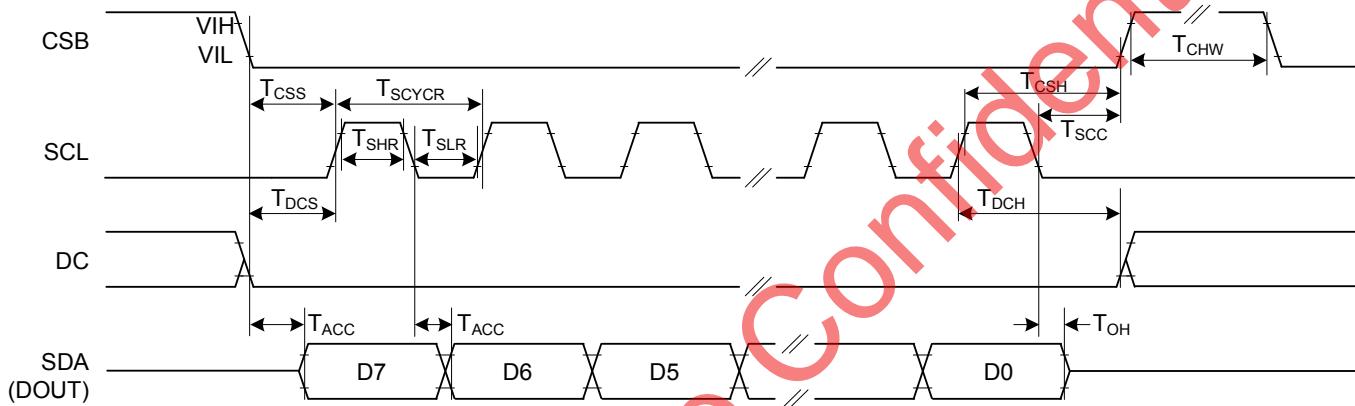
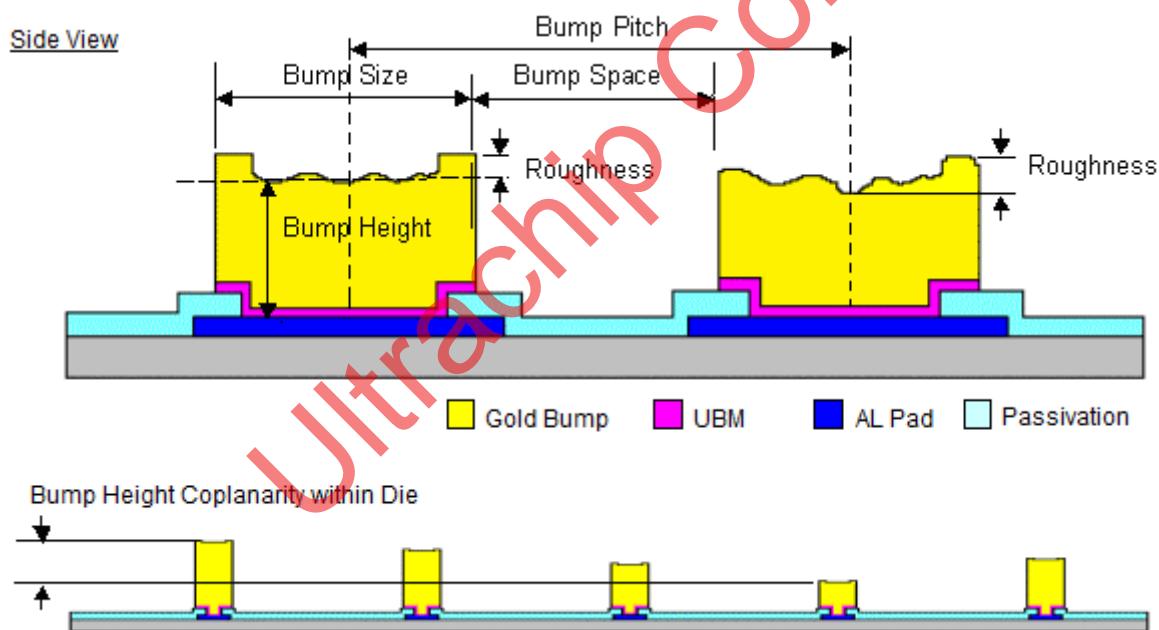


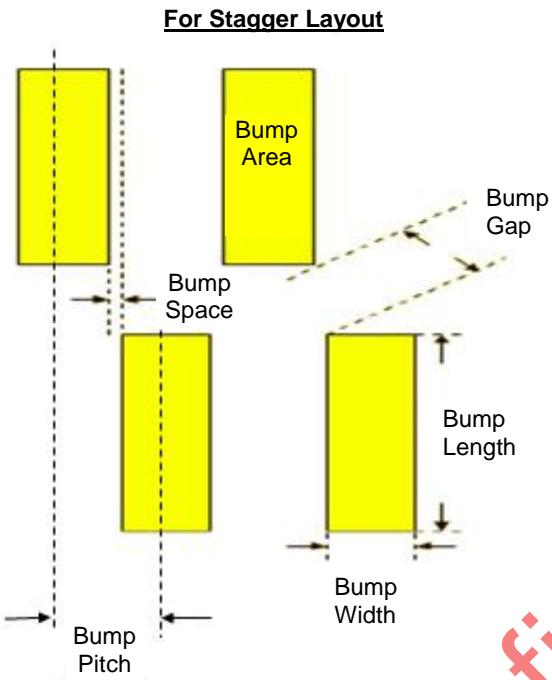
Figure: 4-wire Serial Interface Characteristics (Read mode)

Symbol	Signal / Parameter	Conditions	Min.	Typ.	Max.	Unit
$T_{CSS}$	CSB	Chip select setup time	60			ns
$T_{CSH}$		Chip select hold time	65			ns
$T_{SCC}$		Chip select setup time	20			ns
$T_{CHW}$		Chip select setup time	40			ns
$T_{SCYCW}$	SCL	Serial clock cycle (Write)	100			ns
$T_{SHW}$		SCL "H" pulse width (Write)	35			ns
$T_{SLW}$		SCL "L" pulse width (Write)	35			ns
$T_{SCYCR}$		Serial clock cycle (Read)	150			ns
$T_{SHR}$	SCL	SCL "H" pulse width (Read)	60			ns
$T_{SLR}$		SCL "L" pulse width (Read)	60			ns
$T_{DCS}$	DC	DC setup time	30			ns
$T_{DCH}$		DC hold time	30			ns
$T_{SDS}$	SDA (DIN)	Data setup time	30			ns
$T_{SDH}$		Data hold time	30			ns
$T_{ACC}$	SDA (DOUT)	Access time			50	ns
$T_{OH}$		Output disable time	15			ns

**PHYSICAL DIMENSIONS**

Die Size:  $(9530 \mu\text{M} \pm 40\mu\text{M}) \times (980 \mu\text{M} \pm 40\mu\text{M})$   
Die Thickness:  $300 \mu\text{M} \pm 20\mu\text{M}$   
 $180 \mu\text{M} \pm 15\mu\text{M}$   
Die TTV:  $(D_{\text{MAX}} - D_{\text{MIN}})$  within die  $\leq 2\mu\text{M}$   
Bump Height:  $15 \mu\text{M} \pm 3\mu\text{M}$   
 $(H_{\text{MAX}} - H_{\text{MIN}})$  within die  $\leq 2\mu\text{M}$   
Bump Size:  $12 \mu\text{M} \times 100 \mu\text{M} \pm 2\mu\text{M}$   
Bump Area:  $1200 \mu\text{M}^2$   
Bump Pitch:  $13 \mu\text{M} \pm 2\mu\text{M}$   
Bump Space:  $1 \mu\text{M} \pm 3\mu\text{M}$   
Hardness:  $65 \text{ Hv} \pm 15\text{Hv}$   
Shear:  $\geq 5\text{g/Mil}^2$   
Coordinate origin: Chip center  
Pad reference: Pad center

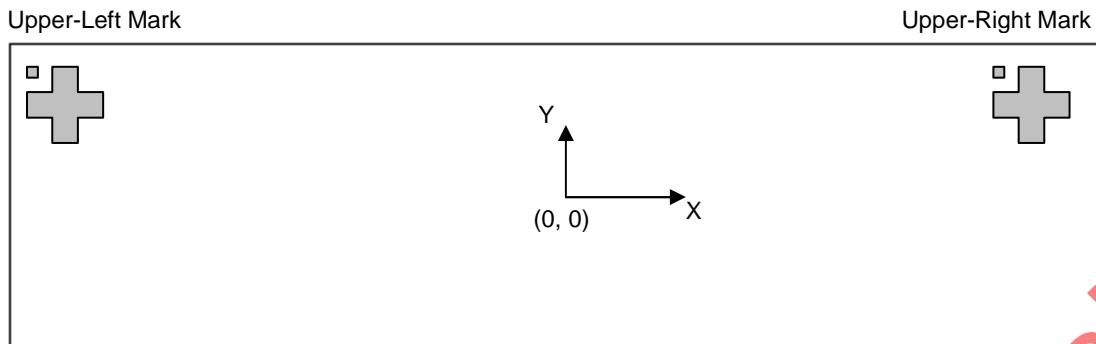




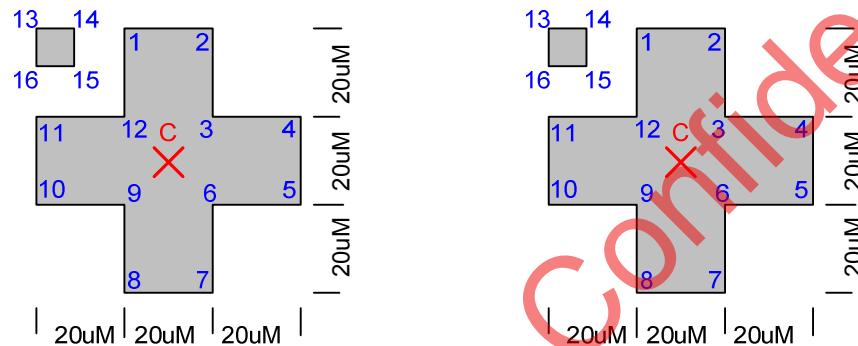
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## ALIGNMENT MARK INFORMATION

### Location:



### Shapes and Points:



### Point Coordinates:

Point	Upper-Left Mark		Upper-Right Mark	
	X	Y	X	Y
Center	-4665	390	4665	390
1	-4675	420	4655	420
2	-4655	420	4675	420
3	-4655	400	4675	400
4	-4635	400	4695	400
5	-4635	380	4695	380
6	-4655	380	4675	380
7	-4655	360	4675	360
8	-4675	360	4655	360
9	-4675	380	4655	380
10	-4695	380	4635	380
11	-4695	400	4635	400
12	-4675	400	4655	400
13	-4695	420	4635	420
14	-4685	420	4645	420
15	-4685	410	4645	410
16	-4695	410	4635	410



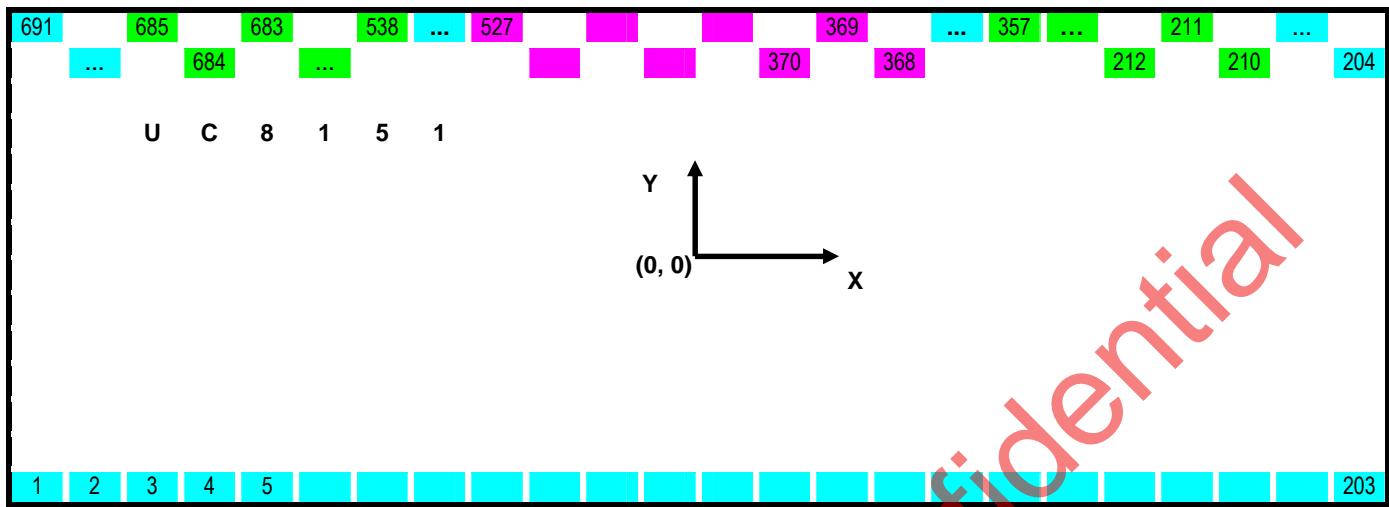






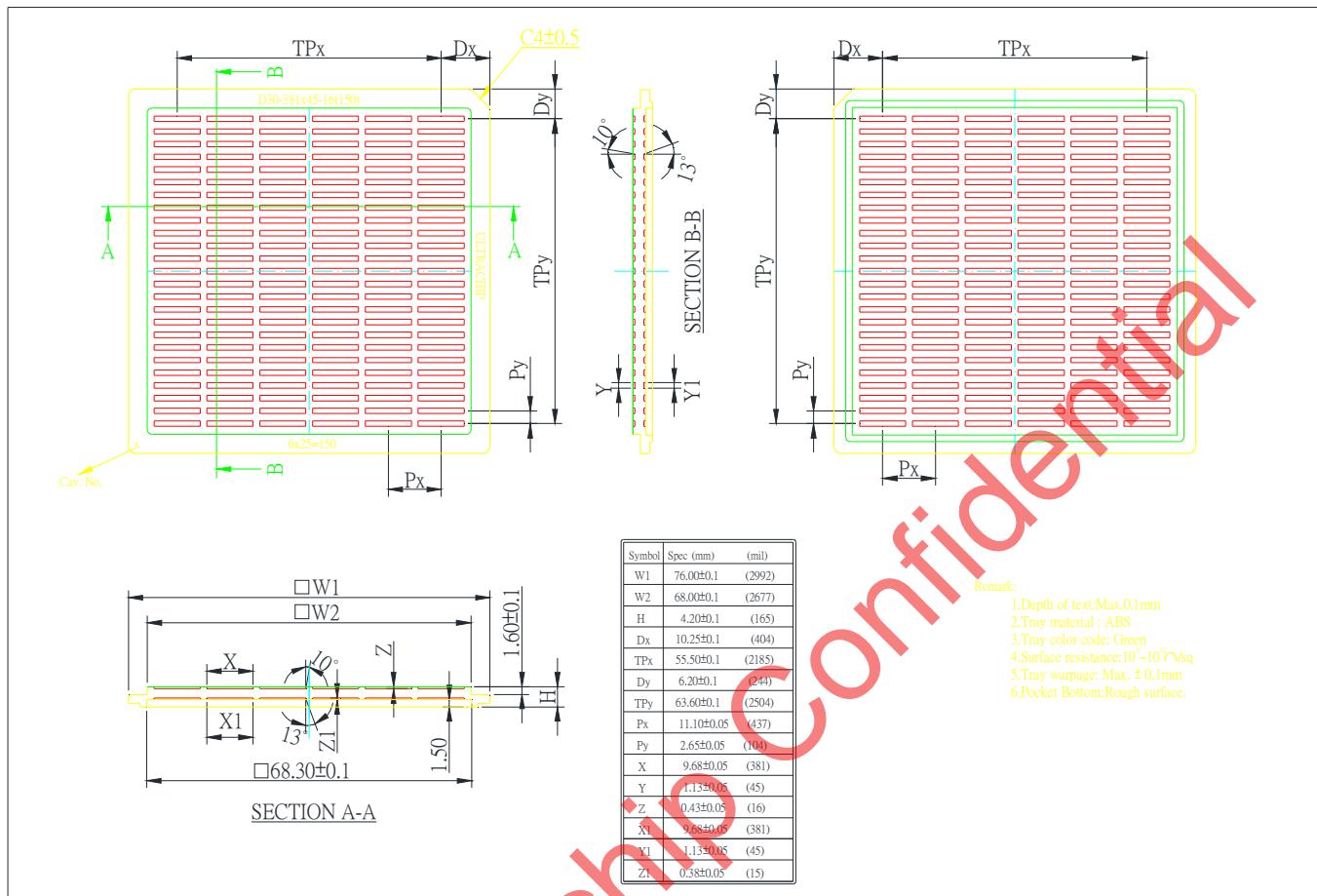




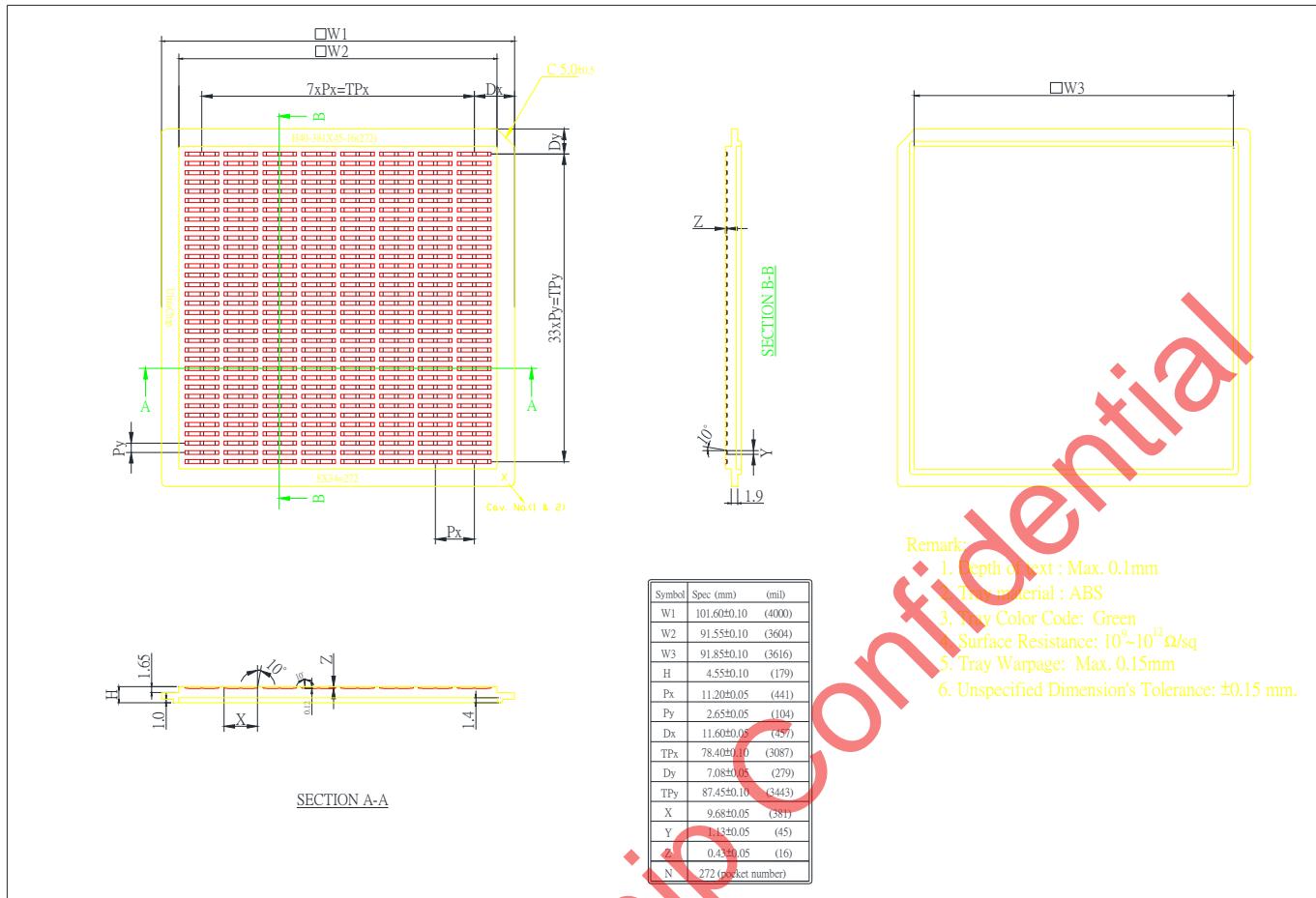
Output Pad Location

## TRAY INFORMATION

3-inch Tray



4-inch Tray



**REVISION HISTORY**

Revision	Contents	Date
0.6	(First Release)	Apr. 7, 2017

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